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(54) **EXTRUSION PROCESS FOR
MANUFACTURING A Z-DIRECTED
COMPONENT FOR A PRINTED CIRCUIT
BOARD**

Related U.S. Application Data

(62) Division of application No. 13/250,812, filed on Sep. 30, 2011, now Pat. No. 8,752,280.

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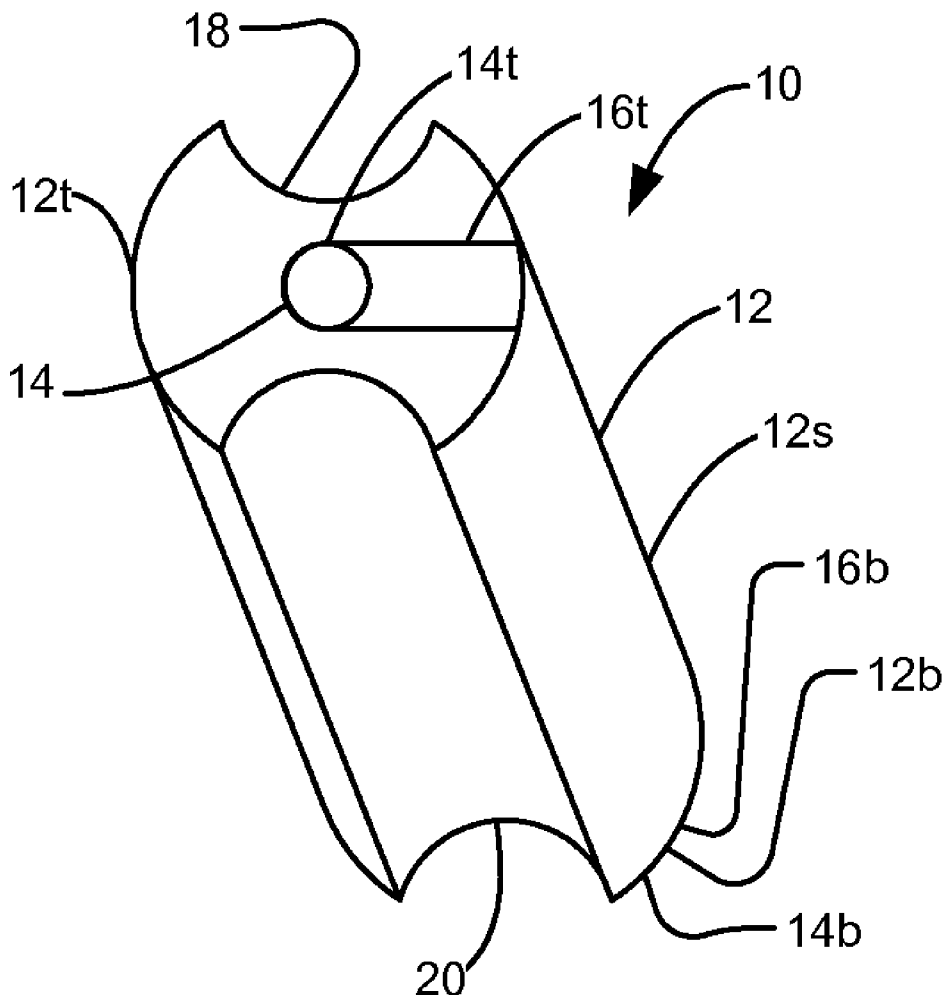
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(57) **ABSTRACT**

A method for manufacturing a Z-directed component for insertion into a mounting hole in a printed circuit board according to one example embodiment includes extruding a substrate material according to the shape of the Z-directed component. A conductive material is then selectively applied to the extruded substrate material and the Z-directed component is formed from the extruded substrate material.

(21) Appl. No.: **14/268,265**

(22) Filed: **May 2, 2014**



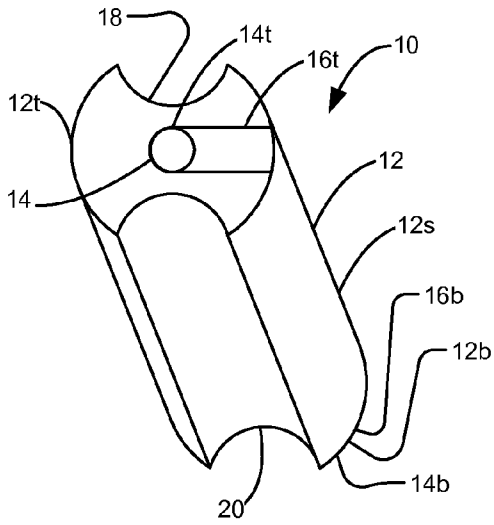


Figure 1

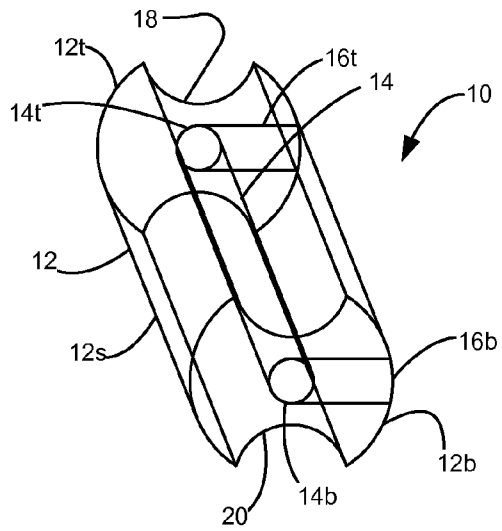


Figure 2

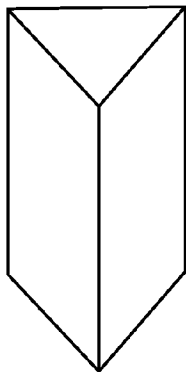


Figure 3A

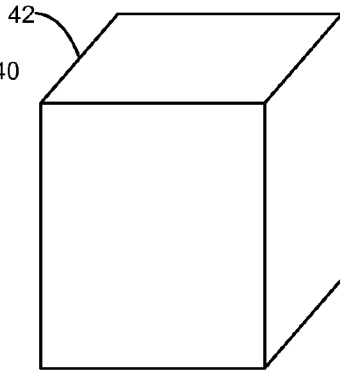


Figure 3B

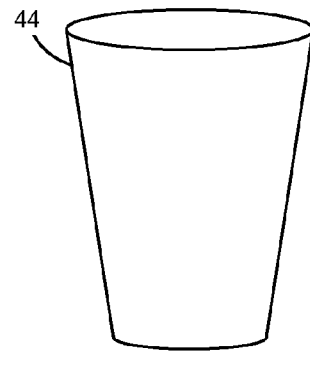


Figure 3C

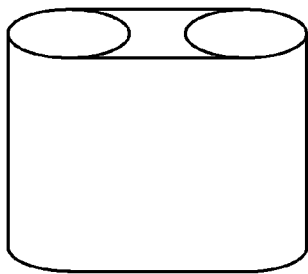


Figure 3D



Figure 3E

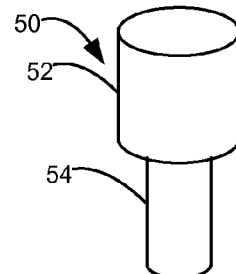


Figure 3F

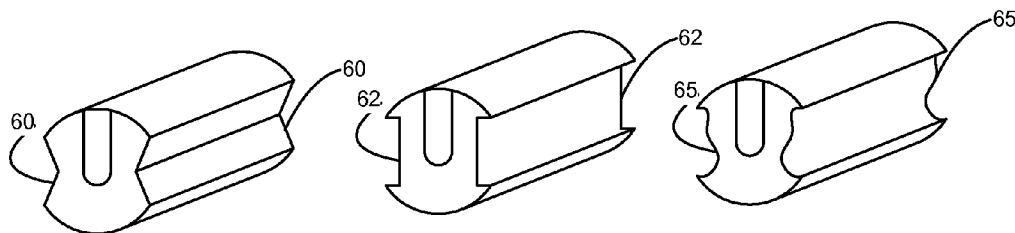


Figure 4A

Figure 4B

Figure 4C

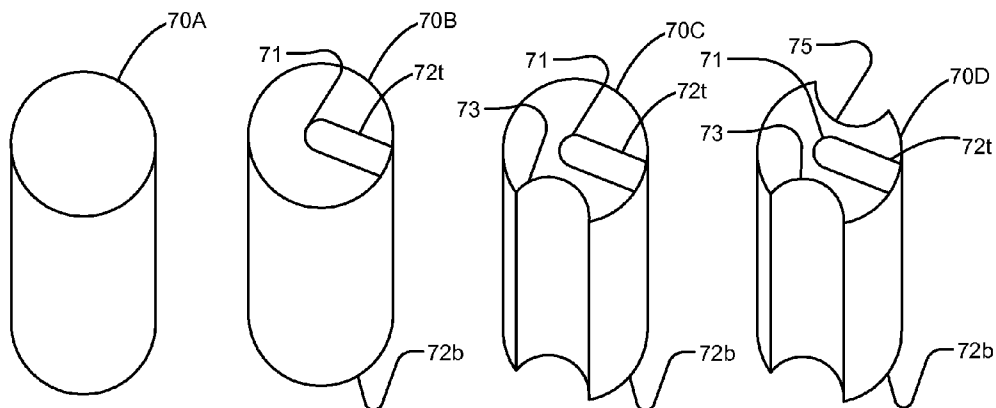


Figure 5A

Figure 5B

Figure 5C

Figure 5D

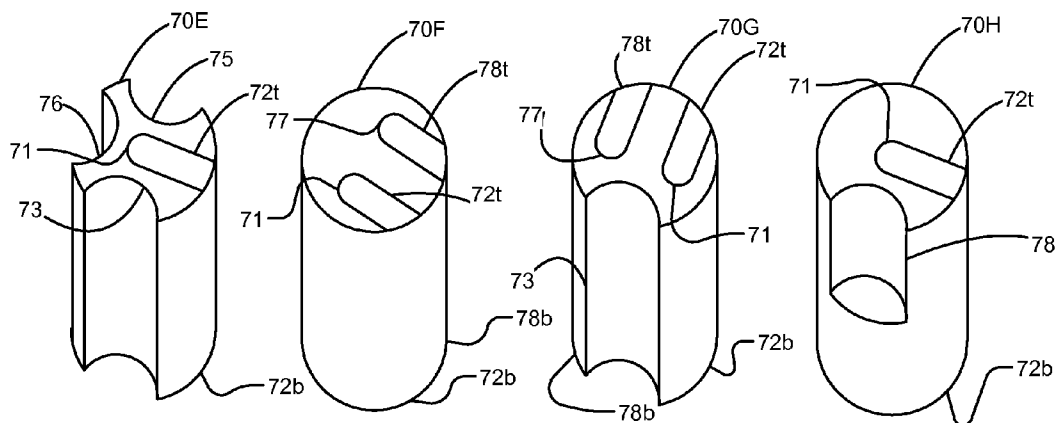


Figure 5E

Figure 5F

Figure 5G

Figure 5H

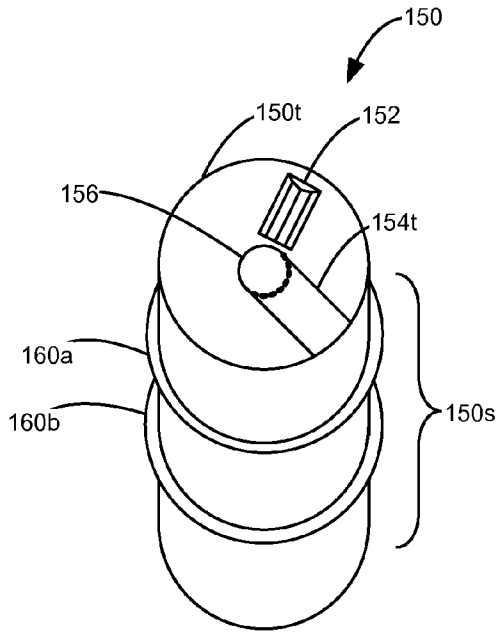


Figure 6A

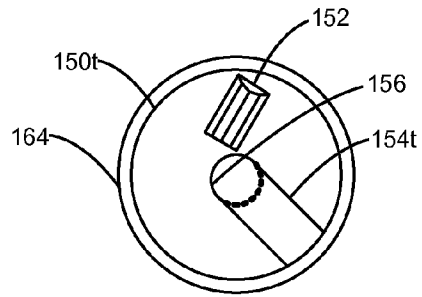


Figure 6B

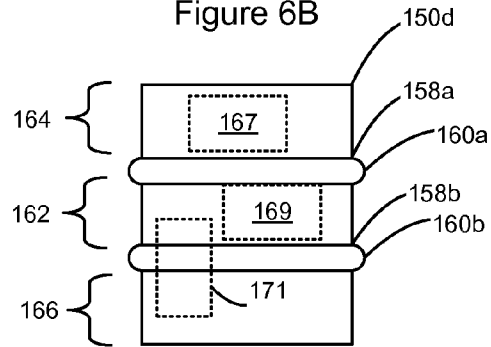


Figure 6C

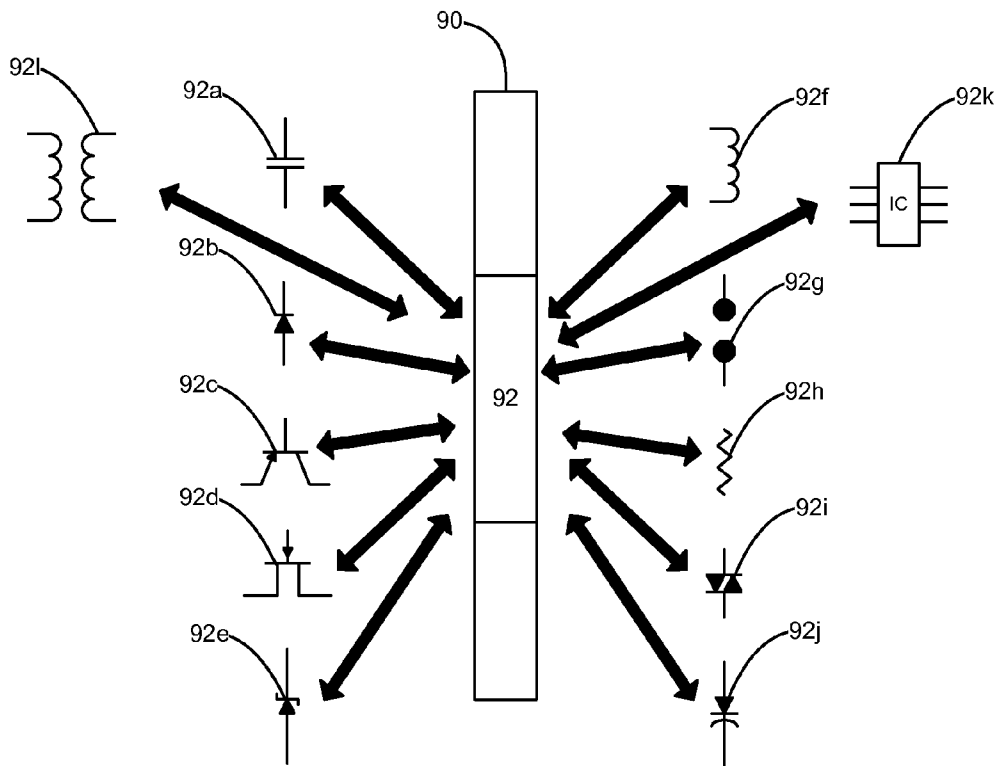


Figure 7

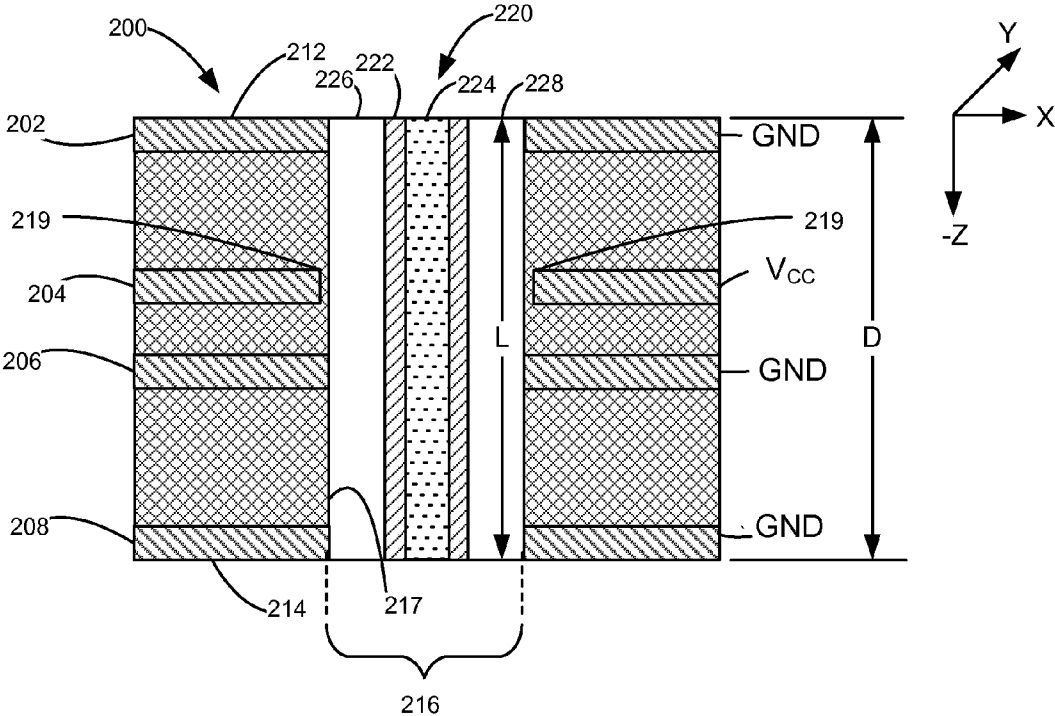


Figure 8

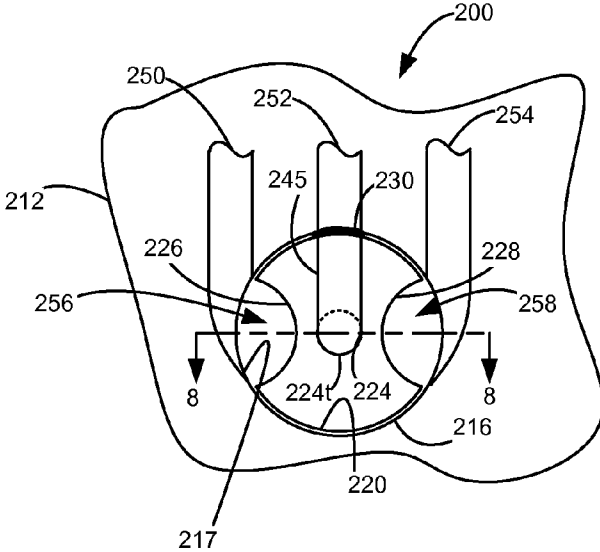


Figure 9

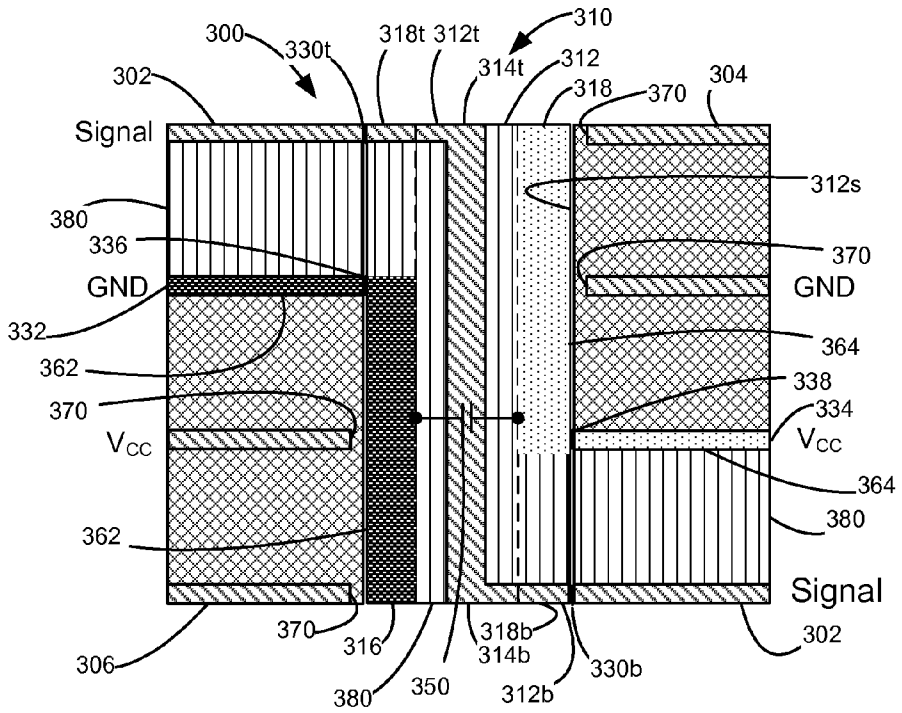


Figure 10

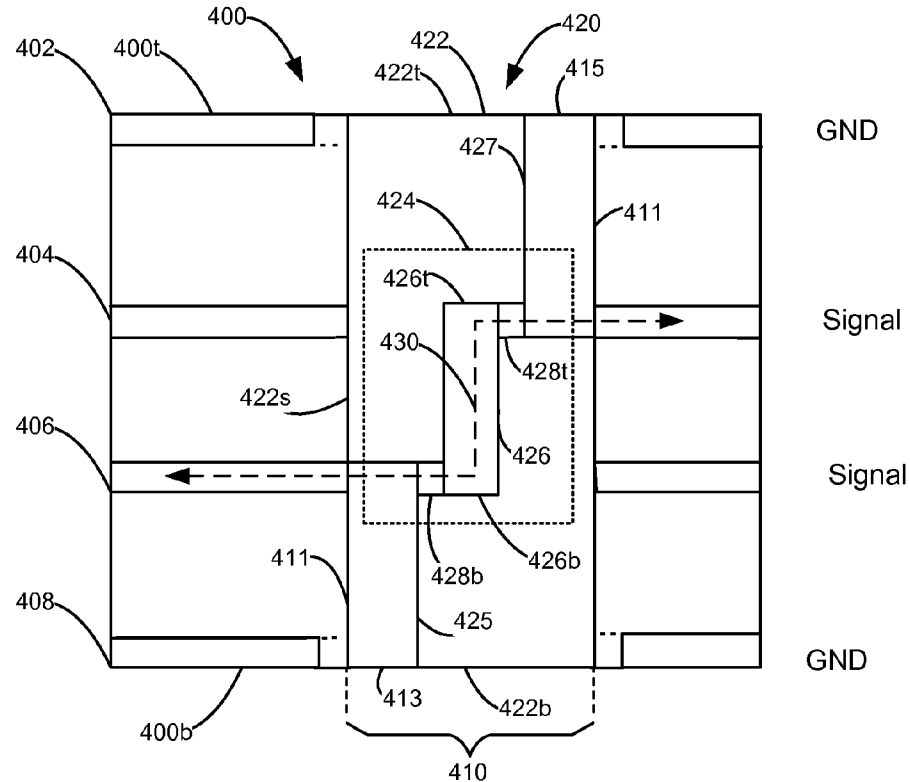


Figure 11

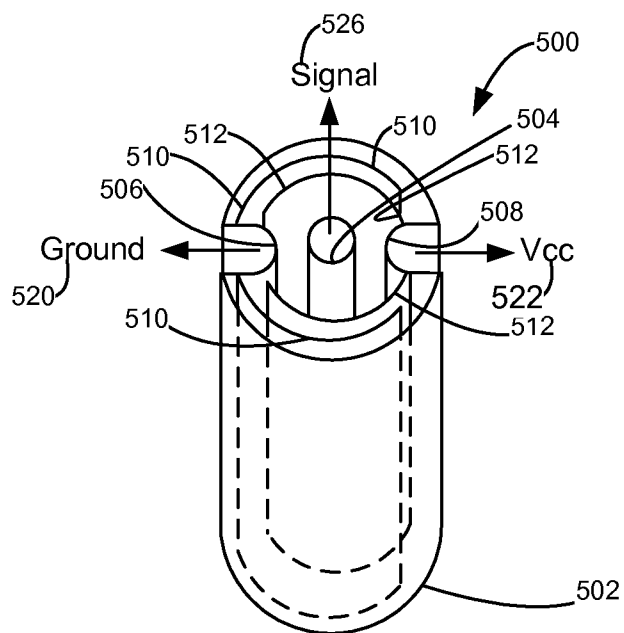


Figure 12

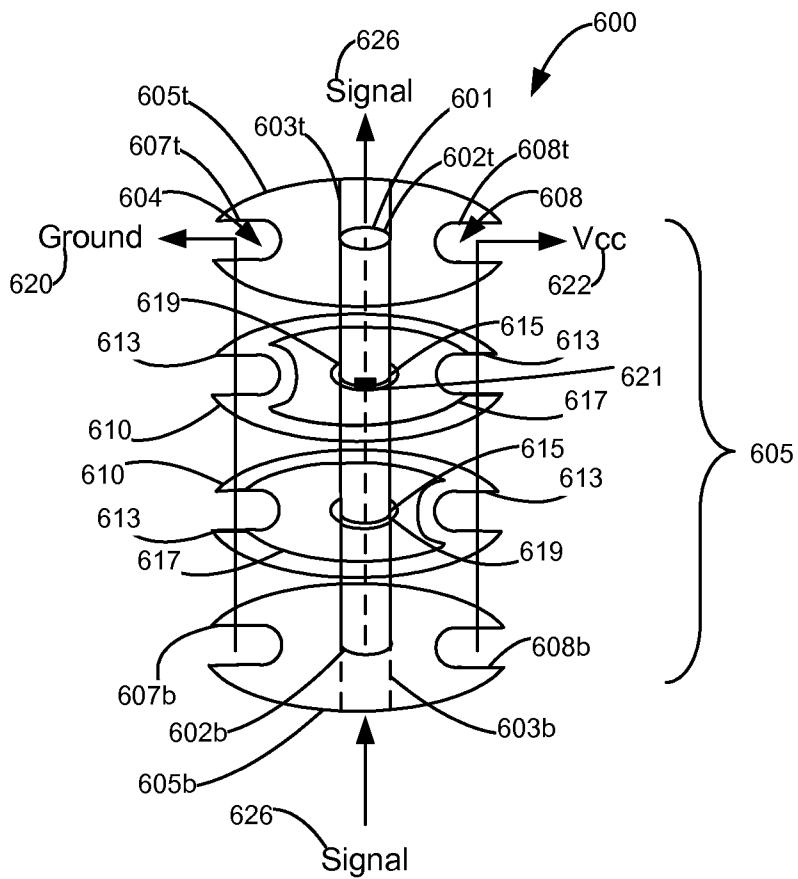


Figure 13

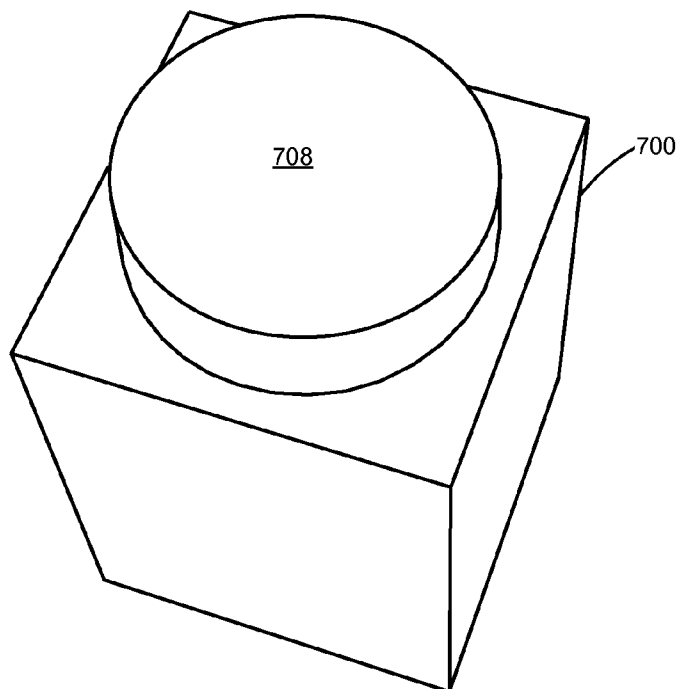


Figure 14A

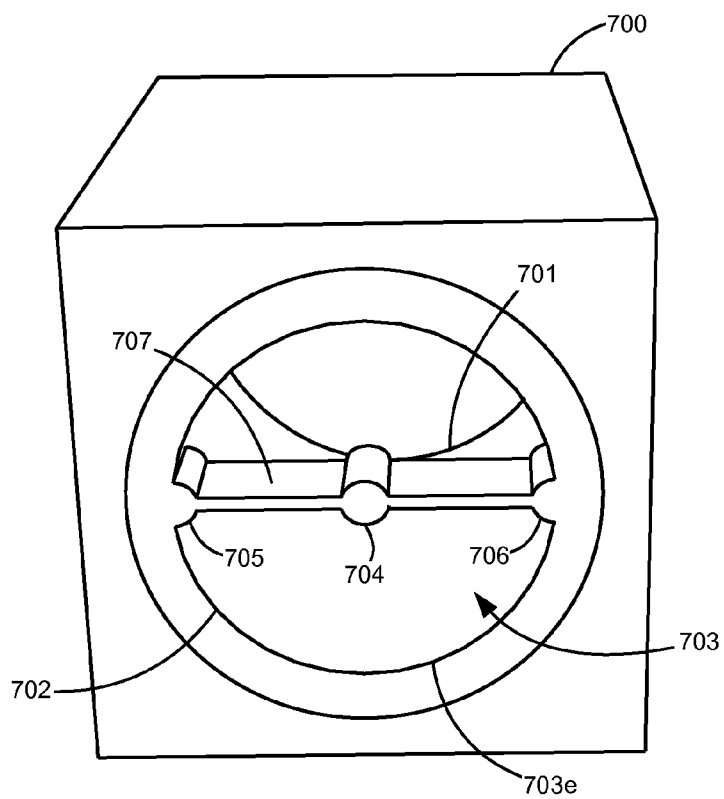


Figure 14B

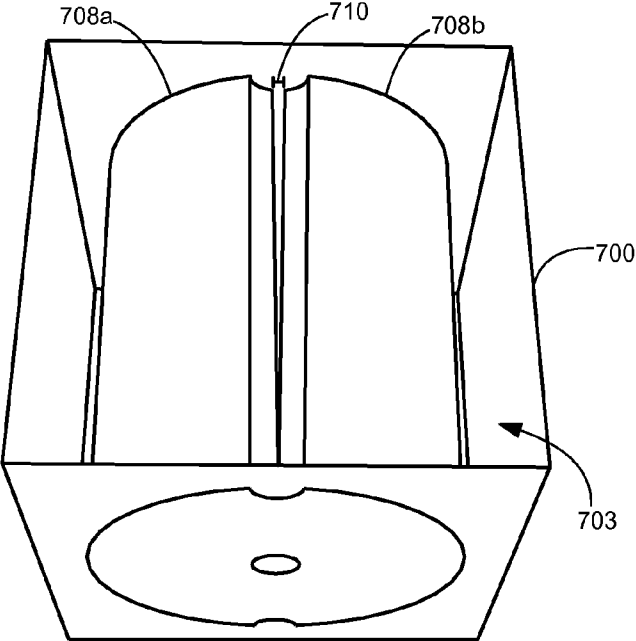


Figure 15A

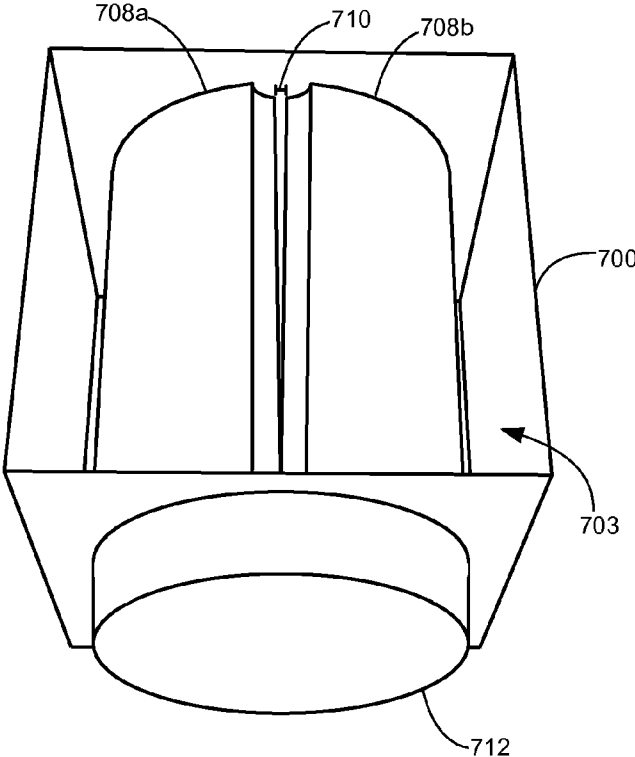


Figure 15B

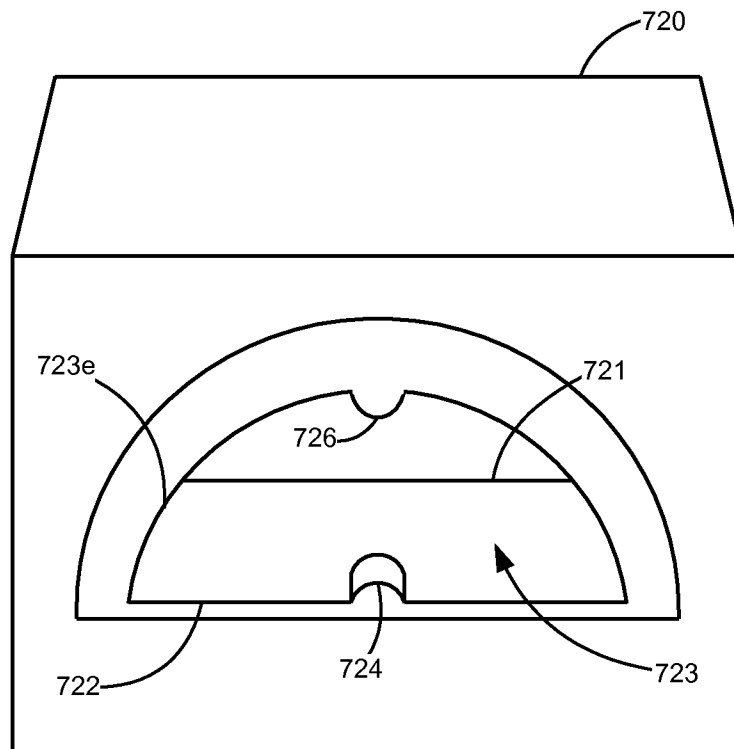


Figure 16

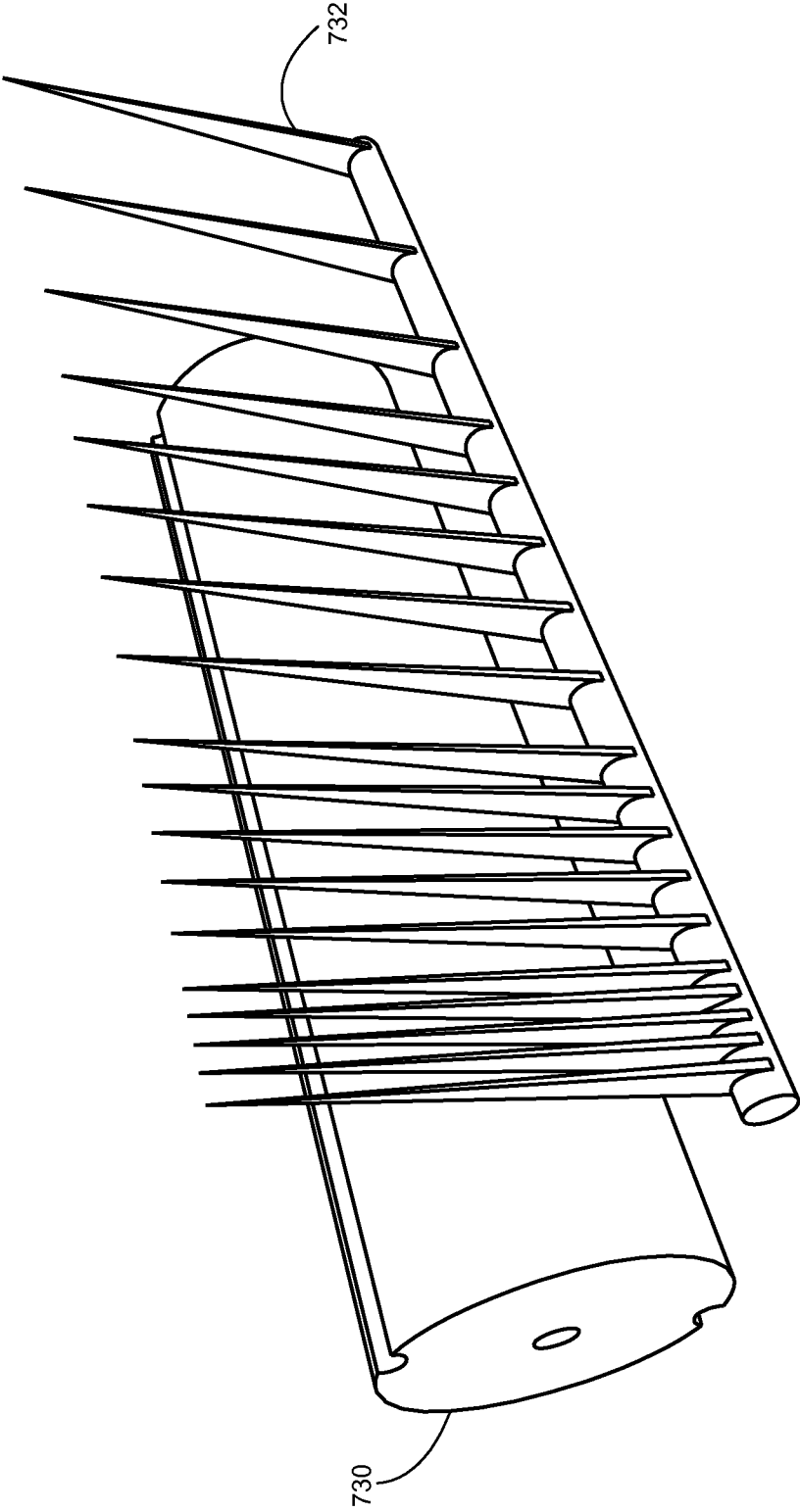


Figure 17

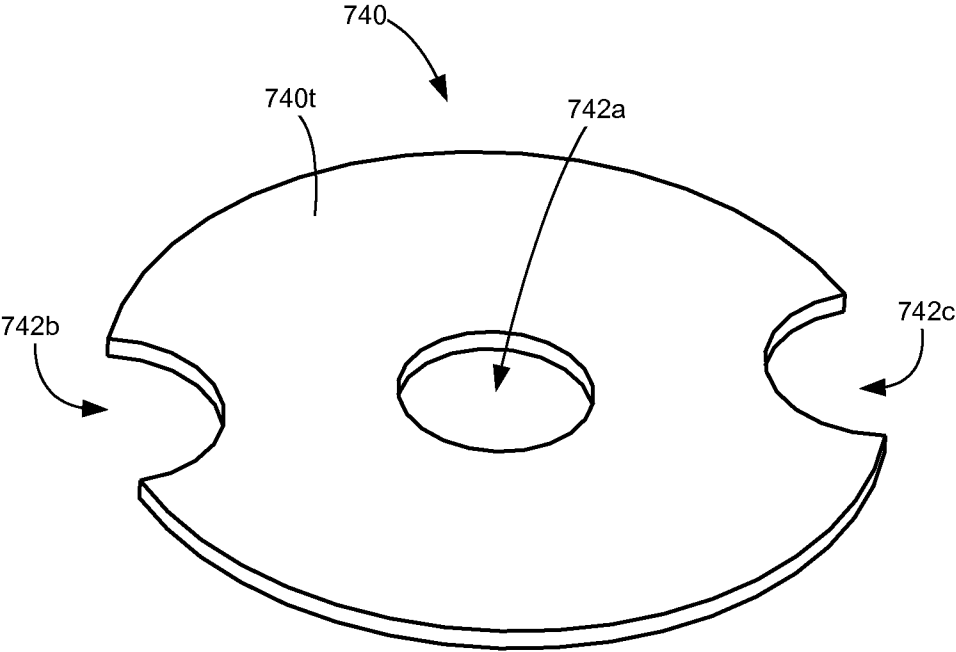


Figure 18

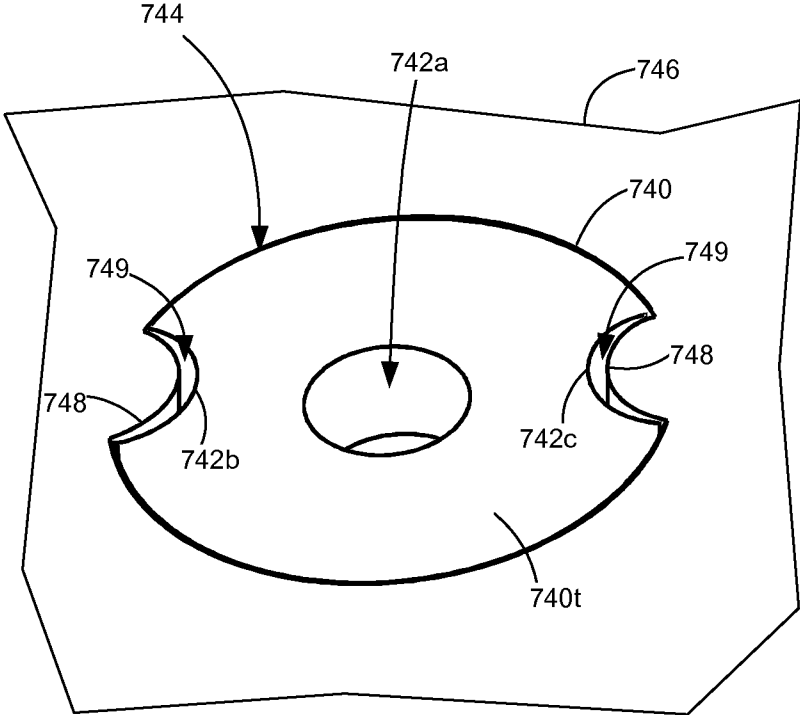


Figure 19

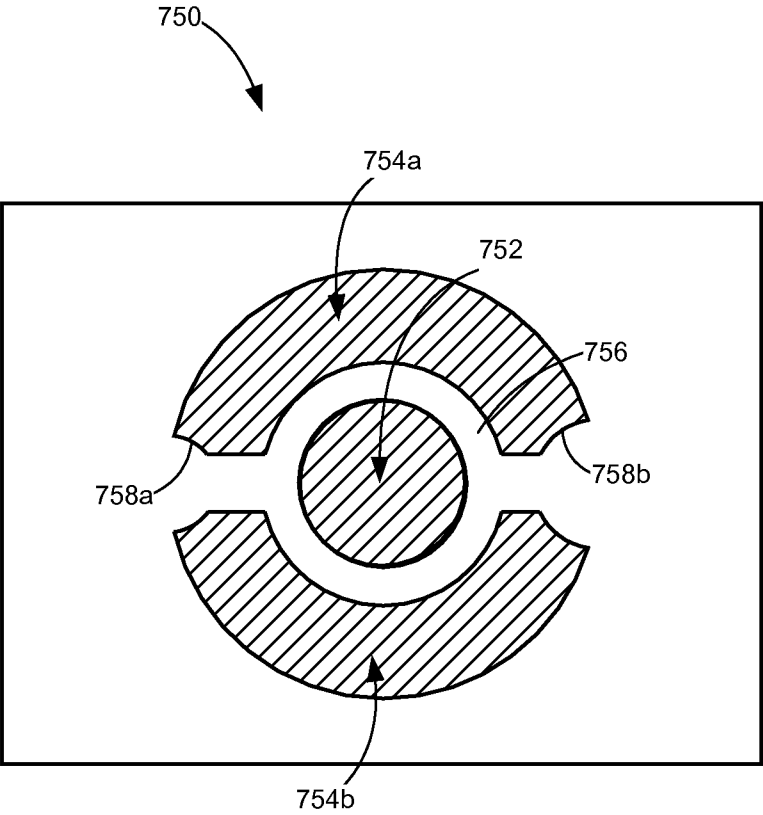


Figure 20

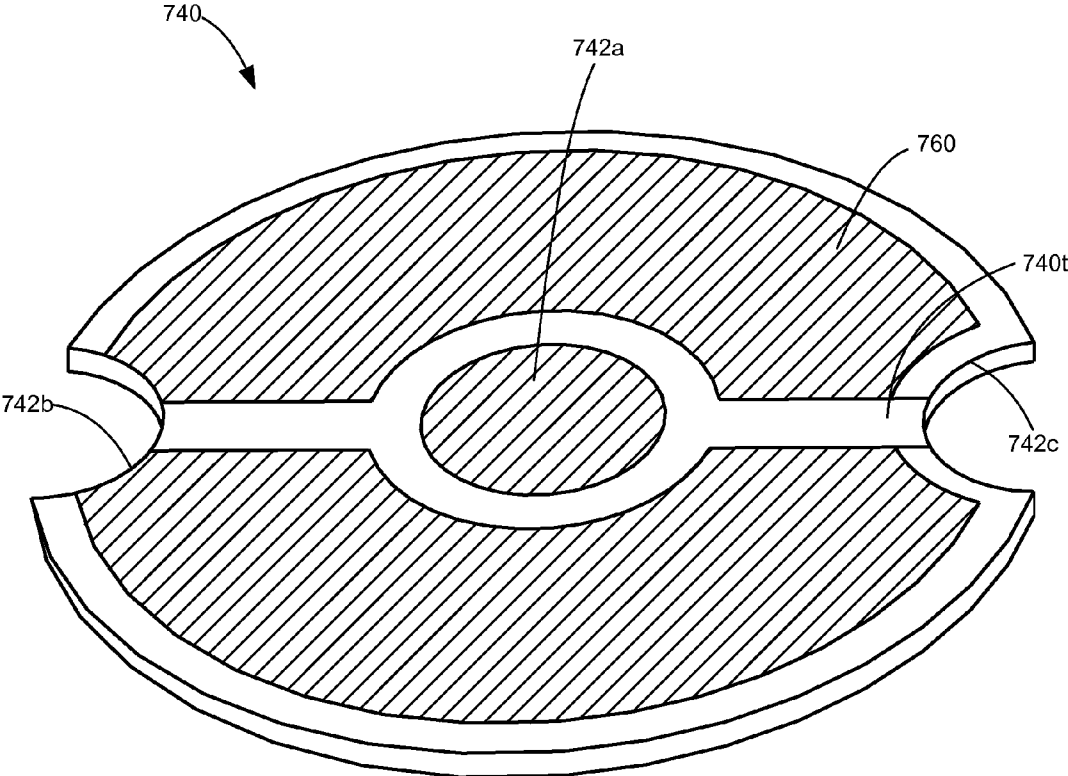


Figure 21

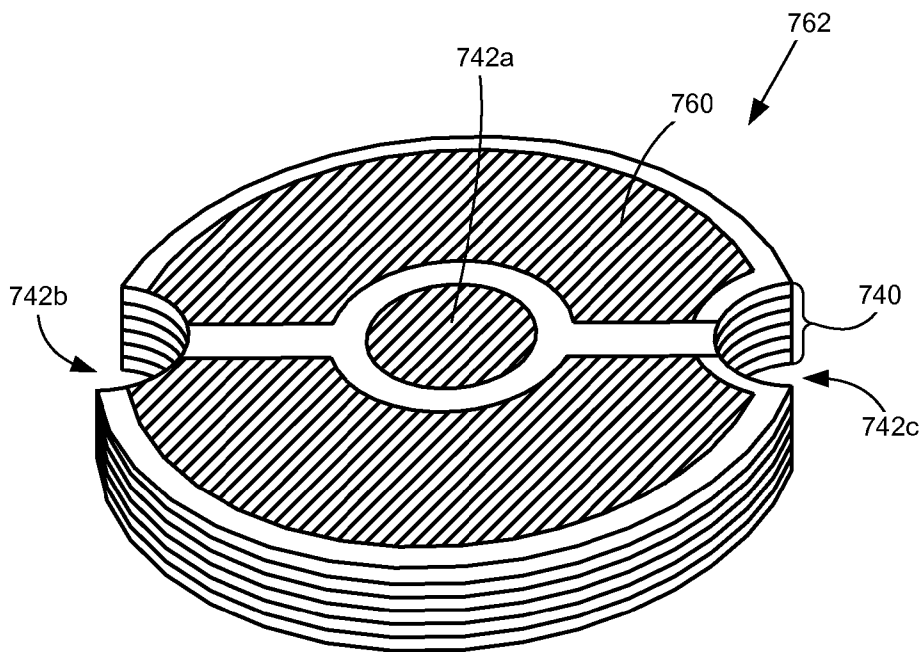


Figure 22A

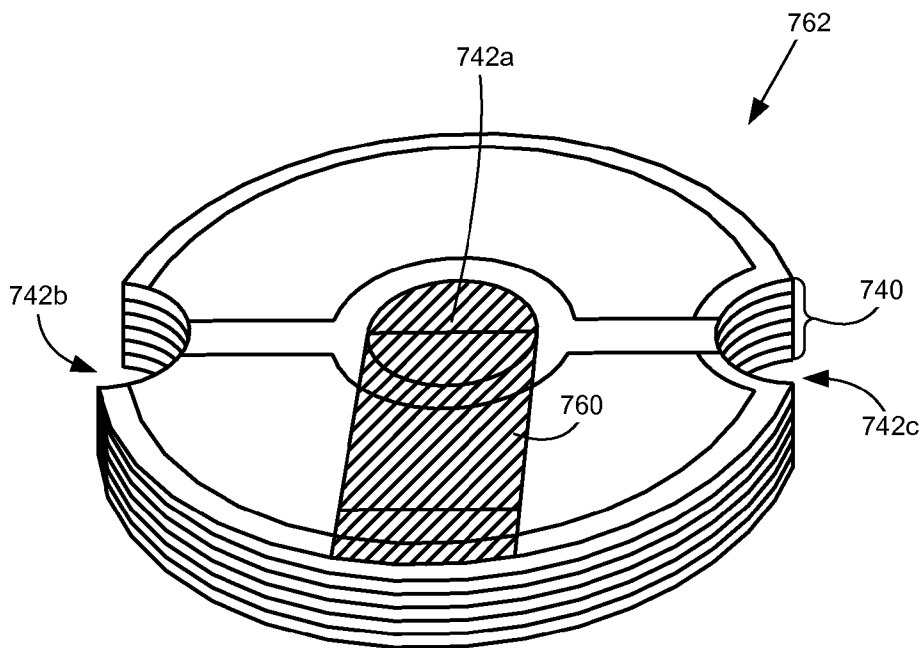


Figure 22B

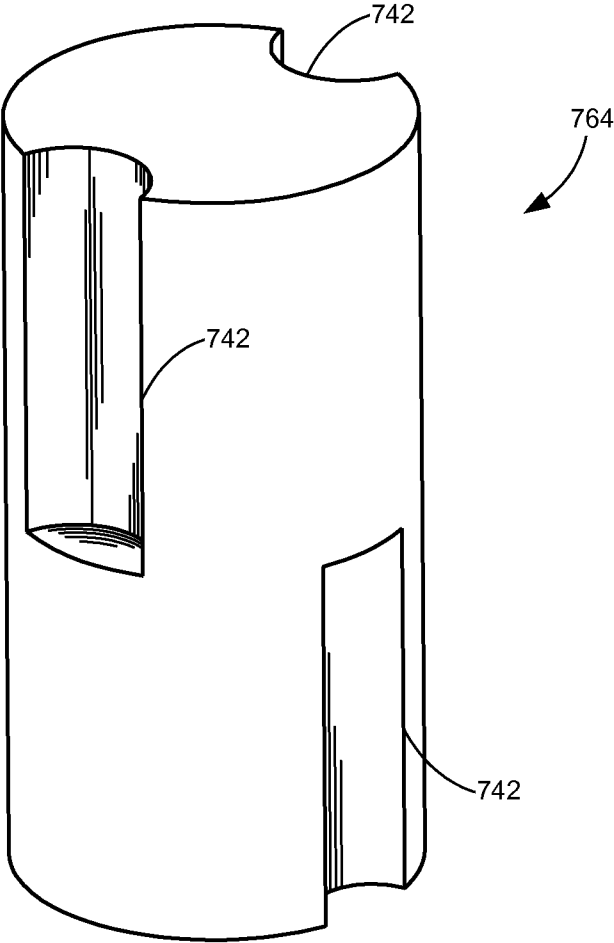


Figure 23

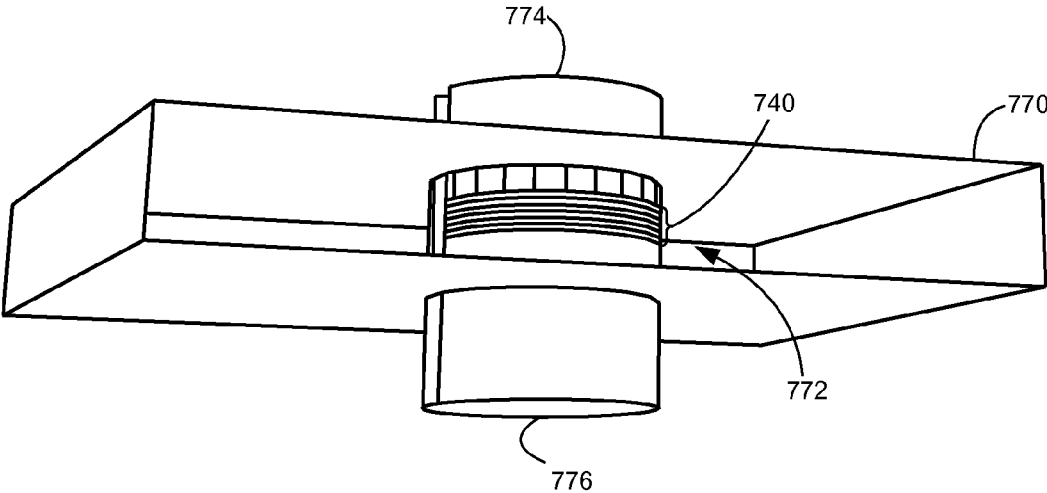


Figure 24

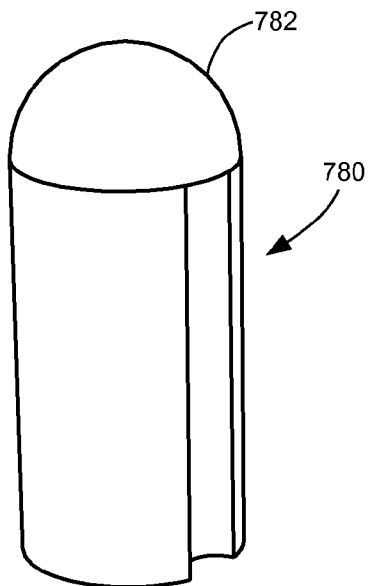


Figure 25A

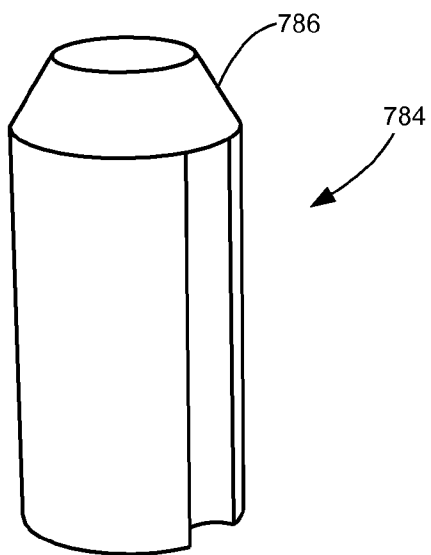


Figure 25B

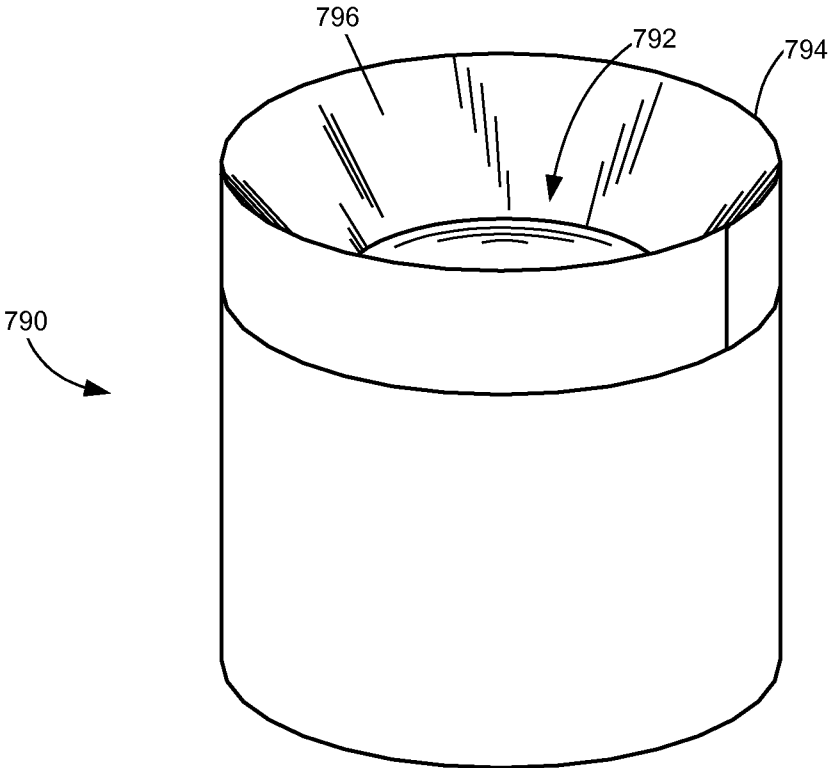


Figure 26

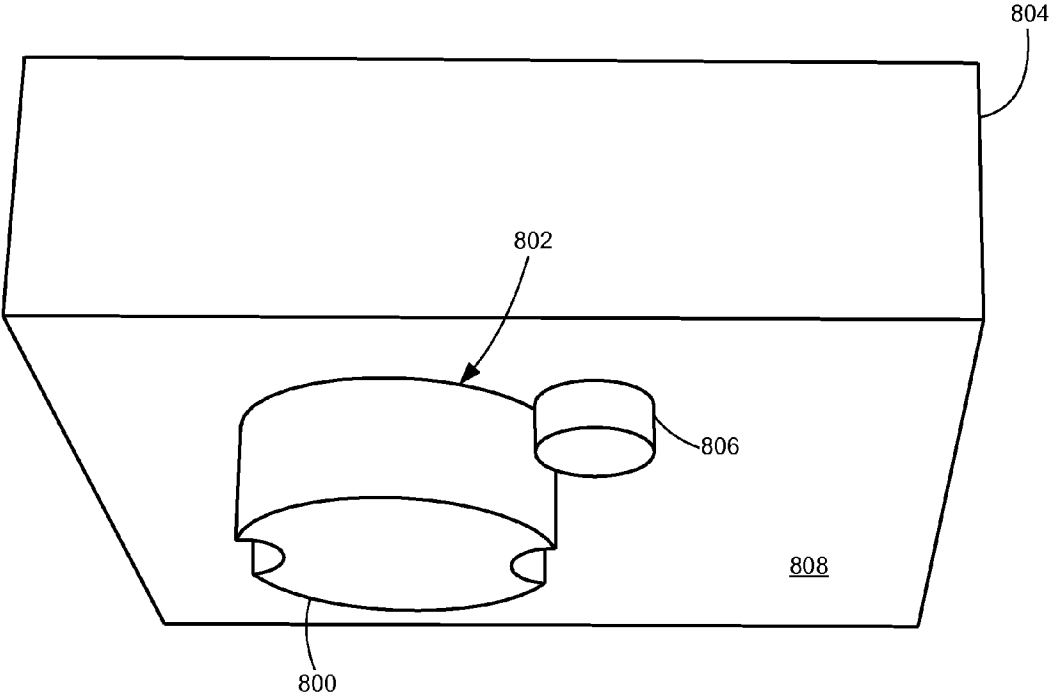


Figure 27

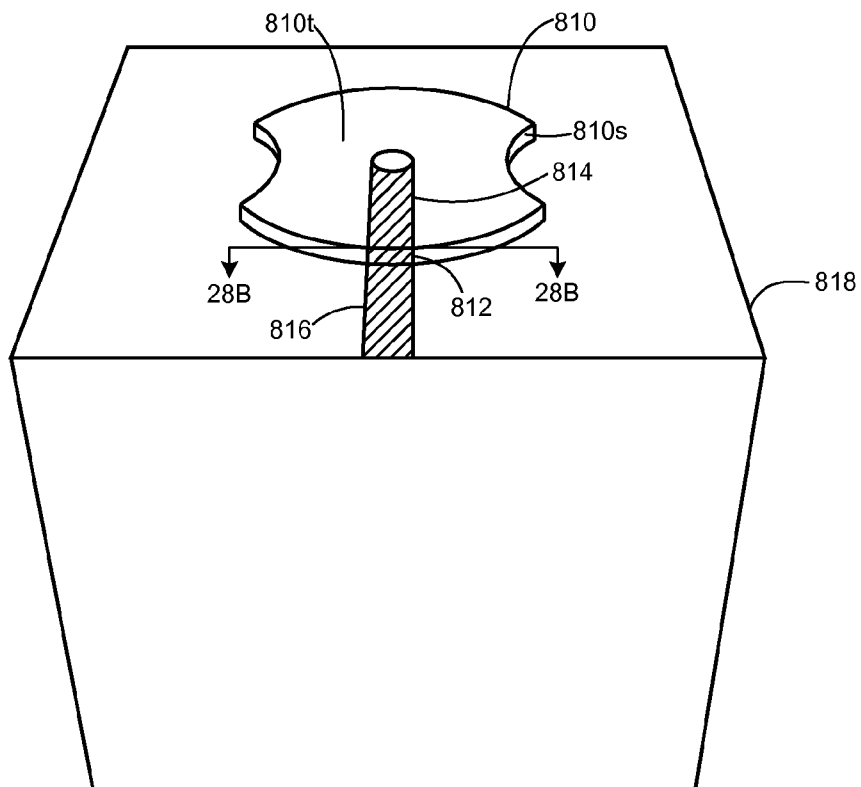


Figure 28A

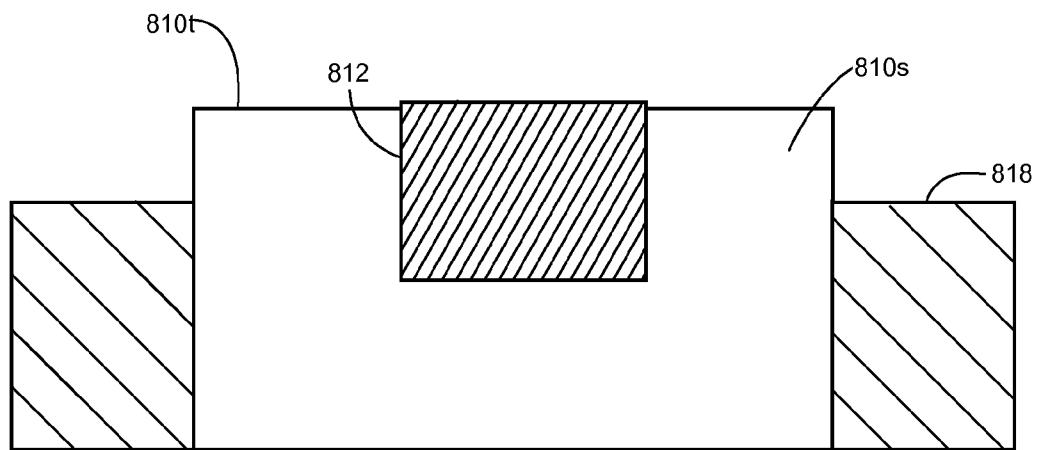


Figure 28B

**EXTRUSION PROCESS FOR
MANUFACTURING A Z-DIRECTED
COMPONENT FOR A PRINTED CIRCUIT
BOARD**

**CROSS REFERENCES TO RELATED
APPLICATIONS**

[0001] This patent application is a divisional application of U.S. patent application Ser. No. 13/250,812, filed Sep. 30, 2011, entitled "Extrusion Process for Manufacturing a Z-Directed Component for a Printed Circuit Board." This patent application is also related to U.S. patent application Ser. No. 13/222,748, filed Aug. 31, 2011, entitled "Die Press Process for Manufacturing a Z-Directed Component for a Printed Circuit Board," U.S. patent application Ser. No. 13/222,418, filed Aug. 31, 2011, entitled "Screening Process for Manufacturing a Z-Directed Component for a Printed Circuit Board," and U.S. patent application Ser. No. 13/222,376, filed Aug. 31, 2011, entitled "Spin Coat Process for Manufacturing a Z-Directed Component for a Printed Circuit Board," and U.S. patent application Ser. No. 13/284,084, filed Oct. 28, 2011, entitled "Continuous Extrusion Process for Manufacturing a Z-Directed Component for a Printed Circuit Board," which are assigned to the assignee of the present application.

BACKGROUND

[0002] 1. Field of the Disclosure

[0003] The present invention relates generally to processes for manufacturing printed circuit board components and more particularly to an extrusion process for manufacturing a Z-directed component for a printed circuit board.

[0004] 2. Description of the Related Art

[0005] The following co-pending United States patent applications, which are assigned to the assignee of the present application, describe various "Z-directed" components that are intended to be embedded or inserted into a printed circuit board ("PCB"): Serial No. 12/508,131 entitled "Z-Directed Components for Printed Circuit Boards," Ser. No. 12/508,145 entitled "Z-Directed Pass-Through Components for Printed Circuit Boards," Ser. No. 12/508,158 entitled "Z-Directed Capacitor Components for Printed Circuit Boards," Ser. No. 12/508,188 entitled "Z-Directed Delay Line Components for Printed Circuit Boards," Ser. No. 12/508,199 entitled "Z-Directed Filter Components for Printed Circuit Boards," Ser. No. 12/508,204 entitled "Z-Directed Ferrite Bead Components for Printed Circuit Boards," Ser. No. 12/508,215 entitled "Z-Directed Switch Components for Printed Circuit Boards," Ser. No. 12/508,236 entitled "Z-Directed Connector Components for Printed Circuit Boards," and Ser. No. 12/508,248 entitled "Z-Directed Variable Value Components for Printed Circuit Boards."

[0006] As densities of components for printed circuit boards have increased and higher frequencies of operation are used, some circuits' designs have become very difficult to achieve. The Z-directed components described in the foregoing patent applications are designed to improve the component densities and frequencies of operation. The Z-directed components occupy less space on the surface of a PCB and for high frequency circuits, e.g. clock rates greater than 1 GHz, allow for higher frequency of operation. The foregoing patent applications describe various types of Z-directed components including, but not limited to, capacitors, delay lines, transis-

tors, switches, and connectors. A process that permits mass production of these components on a commercial scale is desired.

SUMMARY

[0007] A method for manufacturing a Z-directed component for insertion into a mounting hole in a printed circuit board according to a first example embodiment includes extruding a substrate material according to the shape of the Z-directed component. A conductive material is then selectively applied to the extruded substrate material and the Z-directed component is formed from the extruded substrate material.

[0008] A method for manufacturing a Z-directed component for insertion into a mounting hole in a printed circuit board according to a second example embodiment includes extruding a substrate material through an extrusion die having a chamber defining the shape of the extruded substrate material. This includes forming at least one channel through the substrate material with a corresponding projection in the extrusion die. The extruded substrate material is divided into a plurality of layers of the Z-directed component according to the thickness of each layer. A conductive material is applied to a surface of at least one of the layers and a stack of the layers is combined to form the Z-directed component.

BRIEF DESCRIPTION OF THE DRAWINGS

[0009] The above-mentioned and other features and advantages of the various embodiments, and the manner of attaining them, will become more apparent and will be better understood by reference to the accompanying drawings.

[0010] FIG. 1 is a perspective view of a Z-directed component according to one example embodiment.

[0011] FIG. 2 is a transparent perspective view of the Z-directed component shown in FIG. 1 illustrating the internal arrangement of elements of the Z-directed component.

[0012] FIGS. 3A-3F are perspective views showing various example shapes for the body of a Z-directed component.

[0013] FIGS. 4A-4C are perspective views showing various example side channel configurations for a Z-directed component.

[0014] FIGS. 5A-5H are perspective views showing various example channel configurations for the body of a Z-directed component.

[0015] FIG. 6A is a perspective view of a Z-directed component having O-rings for connecting to internal layers of a PCB and having a body having regions comprised of similar and/or dissimilar materials according to one example embodiment.

[0016] FIG. 6B is a top plan view of the Z-directed component shown in FIG. 6A.

[0017] FIG. 6C is a schematic side elevation view of the Z-directed component shown in FIG. 6A.

[0018] FIG. 7 is a schematic illustration of various example elements or electronic components that may be provided within the body of a Z-directed component in series with a conductive channel.

[0019] FIG. 8 is a schematic cross-sectional view of a Z-directed component flush mounted in a PCB showing conductive traces and connections to the Z-directed component according to one example embodiment.

[0020] FIG. 9 is a top plan view of the Z-directed component and PCB shown in FIG. 8.

[0021] FIG. 10 is a schematic cross-sectional view of a Z-directed component flush mounted in a PCB showing ground loops for the Z-directed component with the Z-directed component further having a decoupling capacitor within its body according to one example embodiment.

[0022] FIG. 11 is a schematic cross-sectional view of a Z-directed component flush mounted in a PCB showing a Z-directed component for transferring a signal trace from one internal layer of a PCB to another internal layer of that PCB according to one example embodiment.

[0023] FIG. 12 is a perspective view of a Z-directed capacitor having semi-cylindrical sheets according to one example embodiment.

[0024] FIG. 13 is an exploded view of another embodiment of a Z-directed capacitor having stacked discs according to one example embodiment.

[0025] FIGS. 14A and 14B are perspective views of an extrusion die for forming the layers of a Z-directed component according to one example embodiment.

[0026] FIG. 15A is a perspective cutaway view showing the recombination of a pair of extruded segments formed by the extrusion die shown in FIGS. 14A and 14B.

[0027] FIG. 15B is a perspective cutaway view showing the use of a movable element to aid in recombining of a pair of extruded segments formed by the extrusion die shown in FIGS. 14A and 14B.

[0028] FIG. 16 is a perspective view of an extrusion die for forming the layers of a Z-directed component according to another example embodiment.

[0029] FIG. 17 is perspective view of a series of blades for dividing extruded substrate material into individual layers according to one example embodiment.

[0030] FIG. 18 is a perspective view of a layer of the Z-directed component formed from the extrusion die shown in FIGS. 14A and 14B.

[0031] FIG. 19 is a perspective view of a layer of a Z-directed component in a constraining plate with a gap formed between a side wall surface of the constraining plate and a side channel of the layer according to one example embodiment.

[0032] FIG. 20 is a schematic view of a mask for applying conductive material to a layer of a Z-directed component according to one example embodiment.

[0033] FIG. 21 is a perspective view of a layer of a Z-directed component having conductive material applied through the mask shown in FIG. 20 to a top surface of the layer.

[0034] FIGS. 22A and 22B are perspective views of opposite ends of a Z-directed decoupling capacitor formed according to an extrusion manufacturing process according to one example embodiment.

[0035] FIG. 23 is a perspective view of a Z-directed component having offset side channels according to one example embodiment.

[0036] FIG. 24 is a perspective cutaway view of a stack of layers of a Z-directed component being compressed in a constraining according to one example embodiment.

[0037] FIG. 25A is a perspective view of a Z-directed component having a dome formed on an end thereof according to one example embodiment.

[0038] FIG. 25B is a perspective view of a Z-directed component having a chamfered end according to one example embodiment.

[0039] FIG. 26 is a perspective view of a plug for forming a taper in an end of a Z-directed component according to one example embodiment.

[0040] FIG. 27 is a perspective view of a bottom surface of a PCB having an adhesive applied thereto in contact with a side surface of a Z-directed component inserted into a mounting hole in the PCB according to one example embodiment.

[0041] FIG. 28A is a perspective view of a Z-directed component inserted into a mounting hole in a PCB, the Z-directed component having a conductive strip applied to a side surface thereof according to one example embodiment.

[0042] FIG. 28B is a side cutaway view of the Z-directed component and PCB shown in FIG. 28A.

DETAILED DESCRIPTION

[0043] The following description and drawings illustrate embodiments sufficiently to enable those skilled in the art to practice the present invention. It is to be understood that the disclosure is not limited to the details of construction and the arrangement of components set forth in the following description or illustrated in the drawings. The invention is capable of other embodiments and of being practiced or of being carried out in various ways. For example, other embodiments may incorporate structural, chronological, electrical, process, and other changes. Examples merely typify possible variations. Individual components and functions are optional unless explicitly required, and the sequence of operations may vary. Portions and features of some embodiments may be included in or substituted for those of others. The scope of the application encompasses the appended claims and all available equivalents. The following description is, therefore, not to be taken in a limited sense and the scope of the present invention is defined by the appended claims.

[0044] Also, it is to be understood that the phraseology and terminology used herein is for the purpose of description and should not be regarded as limiting. The use of “including,” “comprising,” or “having” and variations thereof herein is meant to encompass the items listed thereafter and equivalents thereof as well as additional items. Unless limited otherwise, the terms “connected,” “coupled,” and “mounted,” and variations thereof herein are used broadly and encompass direct and indirect connections, couplings, and mountings. In addition, the terms “connected” and “coupled” and variations thereof are not restricted to physical or mechanical connections or couplings.

[0045] Overview of Z-Directed Components

[0046] An X-Y-Z frame of reference is used herein. The X and Y axes describe the plane defined by the face of a printed circuit board. The Z-axis describes a direction perpendicular to the plane of the circuit board. The top surface of the PCB has a zero Z-value. A component with a negative Z-direction value indicates that the component is inserted into the top surface of the PCB. Such a component may be above (extend past), flush with, or recessed below either the top surface and/or the bottom surface of the PCB. A component having both a positive and negative Z-direction value indicates that the component is partially inserted into the surface of the PCB. The Z-directed components are intended to be inserted into a hole or recess in a printed circuit board. Depending on the shape and length of the component(s), more than one Z-directed component may be inserted into a single mounting hole in the PCB, such as being stacked together or positioned side by side. The hole may be a through hole (a hole from the top surface through to the bottom surface), a blind hole (an

opening or recess through either the top or bottom surface into an interior portion or internal layer of the PCB) or an internal cavity such that the Z-directed component is embedded within the PCB.

[0047] For a PCB having conductive traces on both external layers, one external layer is termed the top surface and the other the bottom surface. Where only one external layer has conductive traces, that external surface is referred to as the top surface. The Z-directed component is referred to as having a top surface, a bottom surface and a side surface. The references to top and bottom surfaces of the Z-directed component conform to the convention used to refer to the top and bottom surfaces of the PCB. The side surface of a Z-directed component extends between the top and bottom surfaces of the PCB and would be adjacent to the wall of the mounting hole in the PCB where the mounting hole is perpendicular to the face of the PCB. This use of top, bottom and side should not be taken as limiting how a Z-directed component may be mounted into a PCB. Although the components are described herein as being mounted in a Z-direction, this does not mean that such components are limited to being inserted into a PCB only along the Z-axis. Z-directed components may be mounted normal to the plane of the PCB from the top or bottom surfaces or both surfaces, mounted at an angle thereto or, depending on the thickness of the PCB and the dimensions of the Z-directed component, inserted into the edge of the PCB between the top and bottom surfaces of the PCB. Further, the Z-directed components may be inserted into the edge of the PCB even if the Z-directed component is wider than the PCB is tall as long as the Z-directed component is held in place.

[0048] The Z-directed components may be made from various combinations of materials commonly used in electronic components. The signal connection paths are made from conductors, which are materials that have high conductivity. Unless otherwise stated, reference to conductivity herein refers to electrical conductivity. Conducting materials include, but are not limited to, copper, gold, aluminum, silver, tin, lead and many others. The Z-directed components may have areas that need to be insulated from other areas by using insulator materials that have low conductivity like plastic, glass, FR4 (epoxy & fiberglass), air, mica, ceramic and others. Capacitors are typically made of two conducting plates separated by an insulator material that has a high permittivity (dielectric constant). Permittivity is a parameter that shows the ability to store electric fields in the materials like ceramic, mica, tantalum and others. A Z-directed component that is constructed as a resistor requires materials that have properties that are between a conductor and insulator having a finite amount of resistivity, which is the reciprocal of conductivity. Materials like carbon, doped semiconductor, nichrome, tin-oxide and others are used for their resistive properties. Inductors are typically made of coils of wires or conductors wrapped around a material with high permeability. Permeability is a parameter that shows the ability to store magnetic fields in the material which may include iron and alloys like nickel-zinc, manganese-zinc, nickel-iron and others. Transistors such as field effect transistors ("FETs") are electronic devices that are made from semiconductors that behave in a nonlinear fashion and are made from silicon, germanium, gallium arsenide and others.

[0049] Throughout the application there are references that discuss different materials, properties of materials or terminology interchangeably as currently used in the art of material science and electrical component design. Because of the flex-

ibility in how a Z-directed component may be employed and the number of materials that may be used, it is also contemplated that Z-directed components may be constructed of materials that have not been discovered or created to date. The body of a Z-directed component will in general be comprised of an insulator material unless otherwise called out in the description for a particular design of a Z-directed component. This material may possess a desired permittivity, e.g., the body of a capacitor will typically be comprised of an insulator material having a relatively high dielectric constant.

[0050] PCBs using a Z-directed component may be constructed to have a single conductive layer or multiple conductive layers as is known. The PCB may have conductive traces on the top surface only, on the bottom surface only, or on both the top and bottom surfaces. In addition, one or more intermediate internal conductive trace layers may also be present in the PCB.

[0051] Connections between a Z-directed component and the traces in or on a PCB may be accomplished by soldering techniques, screening techniques, extruding techniques or plating techniques known in the art. Depending on the application, solder pastes and conductive adhesives may be used. In some configurations, compressive conductive members may be used to interconnect a Z-directed component to conductive traces found on the PCB.

[0052] The most general form of a Z-directed component comprises a body having a top surface, a bottom surface and a side surface, a cross-sectional shape that is insertable into a mounting hole of a given depth D within a PCB with a portion of the body comprising an insulator material. All of the embodiments described herein for Z-directed components are based on this general form.

[0053] FIGS. 1 and 2 show an embodiment of a Z-directed component. In this embodiment, Z-directed component 10 includes a generally cylindrical body 12 having a top surface 12*t*, a bottom surface 12*b*, a side surface 12*s*, and a length L generally corresponding to the depth D of the mounting hole. The length L can be less than, equal to or greater than the depth D. In the former two cases, Z-directed component 10 would in one case be below at least one of the top and bottom surfaces of the PCB and in the other it may be flush with the two surfaces of the PCB. Where length L is greater than depth D, Z-directed component 10 would not be flush mounted with at least one of the top and bottom surfaces of the PCB. However, with this non-flush mount, Z-directed component 10 would be capable of being used to interconnect to another component or another PCB that is positioned nearby. The mounting hole is typically a through-hole extending between the top and bottom surfaces of the PCB but it may also be a blind hole. When recessed below the surface of the PCB, additional resist areas may be required in the hole of the PCB to keep from plating the entire circumferential area around the hole.

[0054] Z-directed component 10 in one form may have at least one conductive channel 14 extending through the length of body 12. At the top and bottom ends 14*t* and 14*b* of conductive channel 14, top and bottom conductive traces 16*t*, 16*b* are provided on the top and bottom end surfaces 12*t*, 12*b* of body 12 and extend from respective ends of the conductive channel 14 to the edge of Z-directed component 10. In this embodiment, body 12 comprises an insulator material. Depending on its function, body 12 of Z-directed component 10 may be made of variety of materials having different properties. These properties include being conductive, resis-

tive, magnetic, dielectric, or semi-conductive or various combinations of properties as described herein. Examples of materials that have the properties are copper, carbon, iron, ceramic or silicon, respectively. Body **12** of Z-directed component **10** may also comprise a number of different networks needed to operate a circuit that will be discussed later.

[0055] One or more longitudinally extending channels or wells may be provided on the side surface of body **12** of Z-directed component **10**. The channel may extend from one of the top surface and the bottom surface of body **12** toward the opposite surface. As illustrated, two concave side wells or channels **18** and **20** are provided in the outer surface of Z-directed component **10** extending the length of body **12**. When plated or soldered, these channels allow electrical connections to be made to Z-directed component **10**, through the PCB, as well as to internal conductive layers within the PCB. The length of side channels **18** or **20** may extend less than the entire length of body **12**.

[0056] FIG. 2 shows the same component as in FIG. 1 but with all the surfaces transparent. Conductive channel **14** is shown as a cylinder extending through the center of Z-directed component **10**. Other shapes may also be used for conductive channel **14**. Traces **16t** and **16b** can be seen extending from ends **14t** and **14b** of conductive channel **14**, respectively, to the edge of body **12**. While traces **16t** and **16b** are shown as being in alignment with one another (zero degrees apart), this is not a requirement and they may be positioned as needed for a particular design. For example, traces **16t** and **16b** may be 180 degrees apart or 90 degrees apart or any other increment.

[0057] The shape of the body of the Z-directed component may be any shape that can fit into a mounting hole in a PCB. FIGS. 3A-3F illustrate possible body shapes for a Z-directed component. FIG. 3A shows a triangular cross-sectional body **40**; FIG. 3B shows a rectangular cross-sectional body **42**; FIG. 3C shows a frusto-conical body **44**; FIG. 3D shows an ovate cross-sectional cylindrical body **46**; and FIG. 3E shows a cylindrical body **48**. FIG. 3F shows a stepped cylindrical body **50** where one portion **52** has a larger diameter than another portion **54**. With this arrangement, the Z-directed component may be mounted on the surface of the PCB while having a section inserted into a mounting hole provided in the PCB. The edges of the Z-directed component may be beveled to help with aligning the Z-directed component for insertion into a mounting hole in a PCB. Other shapes and combinations of those illustrated may also be used for a Z-directed component as desired.

[0058] For a Z-directed component, the channels for plating can be of various cross-sectional shapes and lengths. The only requirement is that plating or solder material make the proper connections to the Z-directed component and corresponding conductive traces in or on the PCB. Side channels **18** or **20** may have, for example, V-, C- or U-shaped cross-sections, semi-circular or elliptical cross-sections. Where more than one channel is provided, each channel may have the same or a different cross-sectional shape. FIGS. 4A-4C illustrate three side channel shapes. In FIG. 4A, V-shaped side channels **60** are shown. In FIG. 4B, U- or C-shaped side channels **62** are shown. In FIG. 4C, wavy or irregular cross-sectional side channel shapes **65** are shown.

[0059] The numbers of layers in a PCB varies from being single sided to being over 22 layers and may have different overall thicknesses that range from less than 0.051 inch to over 0.093 inch or more. Where a flush mount is desired, the

length of the Z-directed component will depend on the thickness of the PCB into which it is intended to be inserted. The Z-directed component's length may also vary depending on the intended function and tolerance of a process. The preferred lengths will be where the Z-directed component is either flush with the surfaces or extends slightly beyond the surface of the PCB. This would keep the plating solution from plating completely around the interior of the PCB hole that may cause a short in some cases. It is possible to add a resist material around the interior of a PCB hole to only allow plating in the desired areas. However, there are some cases where it is desired to completely plate around the interior of a PCB hole above and below the Z-directed component. For example, if the top layer of the PCB is a V_{CC} plane and the bottom layer is a GND plane then a decoupling capacitor would have lower impedance if the connection used a greater volume of copper to make the connection.

[0060] There are a number of features that can be added to a Z-directed component to create different mechanical and electrical characteristics. The number of channels or conductors can be varied from zero to any number that can maintain enough strength to take the stresses of insertion, plating, manufacturing processes and operation of the PCB in its intended environment. The outer surface of a Z-directed component may have a coating that glues it in place. Flanges or radial projections may also be used to prevent over or under insertion of a Z-directed component into the mounting hole, particularly where the mounting hole is a through-hole. A surface coating material may also be used to promote or impede migration of the plating or solder material. Various locating or orienting features may be provided such as a recess or projection, or a visual or magnetic indicator on an end surface of the Z-directed component. Further, a connecting feature such as a conductive pad, a spring loaded style pogo-pin or even a simple spring may be included to add an additional electrical connection (such as frame ground) point to a PCB.

[0061] A Z-directed component may take on several roles depending on the number of ports or terminals needed to make connections to the PCB. Some possibilities are shown in FIGS. 5A-H. FIG. 5A is a Z-directed component configured as 0-port device **70A** used as a plug so that if a filter or a component is optional then the plug stops the hole from being plated. After the PCB has been manufactured, the 0-port device **70A** may be removed and another Z-directed component may be inserted, plated and connected to the circuit. FIGS. 5B-5H illustrate various configurations useful for multi-terminal devices such as resistors, diodes, transistors, and/or clock circuits. FIG. 5B shows a 1-port or single signal Z-directed component **70B** having a conductive channel **71** through a center portion of the component connected to top and bottom conductive traces **72t**, **72b**. FIG. 5C shows a 1-port 1-channel Z-directed component **70C** where one plated side well or channel **73** is provided in addition to conductive channel **71** through the component, which is connected to top and bottom conductive traces **72t** and **72b**. FIG. 5D shows a Z-directed component **70D** having two side wells **73** and **75** in addition to conductive channel **71** through the component which is connected to top and bottom traces **72t**, **72b**. The Z-directed component **70E** of FIG. 5E has three side wells **73**, **75** and **76** in addition to conductive channel **71** through the component, which is connected to top and bottom traces **72t**, **72b**. FIG. 5F shows Z-directed component **70F** having two conductive channels **71** and **77** through the com-

ponent each with their respective top and bottom traces **72t**, **72b** and **78t**, **78b** and no side channels or wells. Z-directed component **70F** is a two signal device to be primarily used for differential signaling. FIG. 5G shows a Z-directed component **70G** having one side well **73** and two conductive channels **71** and **77** each with their respective top and bottom traces **72t**, **72b** and **78t**, **78b**. FIG. 5H shows Z-directed component **70H** having one conductive channel **71** with top and bottom traces **72t**, **72b** and a blind well or partial well **78** extending from the top surface along a portion of the side surface that will allow the plating material or solder to stop at a given depth. For one skilled in the art, the number of wells and signals is only limited by the space, required well or channel sizes.

[0062] FIGS. 6A-C illustrate another configuration for a Z-directed component utilizing O-rings for use in a PCB having a top and bottom conductive layer and at least one internal conductive layer. Z-directed component **150** is shown having on its top surface **150t**, a locating feature **152** and a conductive top trace **154t** extending between a conductive channel **156** and the edge of body **150d** on its top surface **150t**. A conductive bottom trace (not shown) is provided on the bottom surface. Conductive channel **156** extends through a portion of the body **150d** as previously described. Located on the side surface **150s** of body **150d** is a least one semi-circular channel or groove. As shown, a pair of axially spaced apart circumferential channels **158a**, **158b** is provided having O-rings **160a**, **160b**, respectively disposed within channels **158a**, **158b**. A portion of the O-rings **160a**, **160b** extend out beyond the side surface **150s** of the body **150d**. O-rings **160a**, **160b** would be positioned adjacent one or more of the internal layers of the PCB to make electrical contact to one or more traces provided at that point in the mounting hole for the Z-directed component. Depending on the design employed, an O-ring would not have to be provided adjacent every internal layer.

[0063] O-rings **160a**, **160b** may be conductive or non-conductive depending on the design of the circuit in which they are used. O-rings **160a**, **160b** preferably would be compressive helping to secure Z-directed component **150** within the mounting hole. The region **162** of body **150d** intermediate O-rings **160a**, **160b** may be comprised of different material than the regions **164** and **166** of the body **150d** outside of the O-rings. For example, if the material of region **162** is of a resistive material and O-rings **160a**, **160b** are conductive then internal circuit board traces in contact with the O-rings **160a**, **160b** see a resistive load.

[0064] Regions **164** and **166** may also be comprised of a material having different properties from each other and region **162**. For example, region **164** may be resistive, region **162** capacitive and region **166** inductive. Each of these regions can be electrically connected to the adjoining layers of the PCB. Further, conductive channel **156** and traces **154t**, **154b** do not need to be provided. So for the illustrated construction, between the top layer of the PCB and the first internal layer from the top, a resistive element may be present in region **164**, a capacitive element between the first internal layer and the second internal layer in region **162** and an inductive element between the second internal layer and the bottom layer of the PCB in region **166**. Accordingly, for a signal transmitted from an internal trace contacting conductive O-ring **160a** to a second internal trace contacting conductive O-ring **160b**, the signal would see an inductive load. The material for regions **162**, **164**, **166** may have properties selected from a group comprising conductive, resistive, mag-

netic, dielectric, capacitive or semi-conductive and combinations thereof. The design may be extended to circuit boards having fewer or more internal layers than that described without departing from the spirit of the invention.

[0065] In addition, regions **162**, **164**, **166** may have electronic components **167**, **169**, **171** embedded therein and connected as described herein. Also, as illustrated for component **171**, a component may be found within one or more regions within the body of a Z-directed component. Internal connections may be provided from embedded components to O-rings **160a**, **160b**. Alternatively, internal connections may be provided from the embedded components to plateable pads provided on the side surface **150s**.

[0066] The various embodiments and features discussed for a Z-directed component are meant to be illustrative and not limiting. A Z-directed component may be made of a bulk material that performs a network function or may have other parts embedded into its body. A Z-directed component may be a multi-terminal device and, therefore, may be used to perform a variety of functions including, but not limited to: transmission lines, delay lines, T filters, decoupling capacitors, inductors, common mode chokes, resistors, differential pair pass throughs, differential ferrite beads, diodes, or ESD protection devices (varistors). Combinations of these functions may be provided within one component.

[0067] FIG. 7 illustrates various example configurations for a conductive channel in a Z-directed component. As shown, channel **90** has a region **92** intermediate the ends comprising a material having properties selected from a group comprising conductive, resistive, magnetic, dielectric, capacitive or semi-conductive properties and combinations thereof. These materials form a variety of components. Additionally, a component may be inserted or embedded into region **92** with portions of the conductive channel extending from the terminals of the component. A capacitor **92a** may be provided in region **92**. Similarly, a diode **92b**, a transistor **92c** such as a MOSFET **92d**, a zener diode **92e**, an inductor **92f**, a surge suppressor **92g**, a resistor **92h**, a diac **92i**, a varactor **92j** and combinations of these items are further examples of materials that may be provided in region **92** of conductive channel **90**. While region **92** is shown as being centered within the conductive channel **90**, it is not limited to that location.

[0068] For a multi-terminal device such as transistor **92c**, MOSFET **92d**, an integrated circuit **92k**, or a transformer **92l**, one portion of the conductive channel may be between the top surface trace and a first terminal of the device and the other portion of the conductive channel between the bottom surface trace and a second terminal of the device. For additional device terminals, additional conductors may be provided in the body of the Z-directed component to allow electrical connection to the remaining terminals or additional conductive traces may be provided within the body of the Z-directed component between the additional terminals and channels on the side surface of the body of a Z-directed component allowing electrical connection to an external conductive trace. Various connection configurations to a multiple terminal device may be used in a Z-directed component.

[0069] Accordingly, those skilled in the art will appreciate that various types of Z-directed components may be utilized including, but not limited to, capacitors, delay lines, transistors, switches, and connectors. For example, FIGS. 8 and 9 illustrate a Z-directed component termed a signal pass-through that is used for passing a signal trace from the top surface of a PCB to the bottom surface.

[0070] Z-Directed Signal Pass-Through Component

[0071] FIG. 8 shows a sectional view taken along line 8-8 in FIG. 9 of a PCB 200 having 4 conductive planes or layers comprising, from top to bottom, a ground (GND) plane or trace 202, a voltage supply plane V_{CC} 204, a second ground GND plane 206 and a third ground GND plane or trace 208 separated by nonconductive material such as a phenolic plastic such as FR4 which is widely used as is known in the art. PCB 200 may be used for high frequency signals. The top and bottom ground planes or traces 202 and 208, respectively, on the top and bottom surfaces 212 and 214, respectively, of PCB 200 are connected to conductive traces leading up to Z-directed component 220. A mounting hole 216 having a depth D in a negative Z direction is provided in PCB 200 for the flush mounting of Z-directed component 220. Here depth D corresponds to the thickness of PCB 200; however, depth D may be less than the thickness of PCB 200 creating a blind hole therein. Mounting hole 216, as illustrated, is a through-hole that is round in cross-section to accommodate Z-directed component 220 but may have cross sections to accommodate the insertion of Z-directed components having other body configurations. In other words, mounting holes are sized so that Z-directed components are insertable therein. For example, a Z-directed component having a cylindrical shape may be inserted into a square mounting hole and vice versa. In the cases where Z-directed component does not make a tight fit, resist materials will have to be added to the areas of the component and PCB where copper plating is not desired.

[0072] Z-directed component 220 is illustrated as a three lead component that is flush mounted with respect to both the top surface 212 and bottom surface 214 of PCB 200. Z-directed component 220 is illustrated as having a generally cylindrical body 222 of a length L. A center conductive channel or lead 224, illustrated as being cylindrical, is shown extending the length of body 222. Two concave side wells or channels 226 and 228, which define the other two leads, are provided on the side surface of Z-directed component 220 extending the length of body 222. Side channels 226 and 228 are plated for making electrical connections to Z-directed component 220 from various layers of PCB 200. As shown, the ground plane traces on layers 202, 206, and 208 of PCB 100 are electrically connected to side channels 226 and 228. V_{CC} plane 204 does not connect to Z-directed component 220 as shown by the gap 219 between V_{CC} plane 204 and wall 217 of mounting hole 216.

[0073] FIG. 9 illustrates a top view of Z-directed component 220 in PCB 200. Three conductive traces 250, 252 and 254 lead up to the edge of wall 217 of mounting hole 216. As illustrated, trace 252 serves as a high-frequency signal trace to be passed from the top surface 212 to the bottom surface 214 of PCB 200 via Z-directed component 220. Conductive traces 250 and 254 serve as ground nets. Center lead or conductive channel 224 is electrically connected to trace 252 on the top surface 212 of PCB 200 by a top trace 245 and plating bridge 230. Top trace 245 on the top surface of Z-directed component 220 extends from the top end 224t of conductive channel 224 to the edge of Z-directed component 220. Although not shown, the bottom side of Z-directed component 220 and bottom surface 214 of PCB 200 is configured in a similar arrangement of traces as shown on top surface 212 of PCB 200 illustrated in FIG. 12. A bottom trace on the bottom surface of Z-directed component 220 extends from bottom of conductive channel 224 to the edge of Z-directed component 220. A plating bridge is used to make the electrical connection

between the bottom trace and another high frequency signal trace provided on the bottom surface of PCB 200. The transmission line impedance of the Z-directed component can be adjusted to match the PCB trace impedance by controlling the conductor sizes and distances between each conductor which improves the high speed performance of the PCB.

[0074] During the plating process, wells 256 and 258 formed between wall 217 of mounting hole 216 and side channels 226 and 228 allow plating material or solder pass from the top surface 212 to the bottom surface 214 electrically interconnecting traces 250 and 254, respectively to side channels 226 and 228, respectively, of Z-directed component 220 and also to similarly situated traces provided on the bottom surface 214 of PCB 200 interconnecting ground planes or traces 202, 206 and 208. The plating is not shown for purposes of illustrating the structure. In this embodiment, V_{CC} plane 204 does not connect to Z-directed component 220.

[0075] One of the challenges for high frequency signal speeds is the reflections and discontinuities due to signal trace transmission line impedance changes. Many PCB layouts try to keep high frequency signals on one layer because of these discontinuities caused by the routing of signal traces through the PCB. Standard vias through a PCB have to be spaced some distance apart which creates high impedance between the signal via and the return signal via or ground via. As illustrated in FIGS. 8 and 9, the Z-directed component and the return ground or signals have a very close and controlled proximity that allow essentially constant impedance from the top surface 212 to the bottom surface 214 of PCB 200.

[0076] A Z-directed signal pass through component may also comprise a decoupling capacitor that will allow the reference plane of a signal to switch from a ground plane, designated GND, to a voltage supply plane, designated V_{CC} , without having a high frequency discontinuity. FIG. 10 shows a cross-sectional view of a typical 4-layer PCB 300 with a signal trace 302 transferring between the top layer 304 and the bottom layer 306. Z-directed component 310, similar to that shown in FIG. 5D, having body 312 connects signal trace 302 through center conductive channel 314. Z-directed component 310 also comprises plated side channels 316 and 318 extending along the side surface 312s of the body 312. The top 314t and bottom 314b of conductive channel 314 are connected to conductive traces 318t and 318b on the top 312t and bottom 312b of body 312. These, in turn, are connected to signal trace 302 via top and bottom plating bridges 330t and 330b. Side channels 316 and 318 are plated to GND plane 332 and V_{CC} plane 334, respectively. Connection points 336 and 338, respectively, illustrate this electrical connection. Schematically illustrated decoupling capacitor 350 is internal to body 312 and is connected between side channels 316 and 318. Decoupling capacitor 350 may be a separate capacitor integrated into the body 312 of Z-directed component 310 or it can be formed by fabricating a portion of the body 312 of Z-directed component 310 from the required materials with dielectric properties between conductive surfaces.

[0077] The path for signal trace 302 is illustrated with diagonal hatching and can be seen to run from top layer 304 to bottom layer 306. GND plane 332 and side channel 316 are electrically connected at 336 with the signal path return indicated by the dark stippling 362. V_{CC} plane 334 and side channel 318 are electrically connected at 338 with the signal path return indicated by the light stippling 364. As is known in the art, where a signal plane or trace is not to be connected to the inserted part, those portions are spaced apart from the

component as shown at 370. Where a signal plane or trace is to be connected to an inserted component, the signal plane or trace is provided at the wall or edge of the opening to allow the plating material or solder to bridge therebetween as illustrated at points 330t, 330b, 336, and 338.

[0078] The vertically hatched portion 380 shows the high speed loop area between the signal trace and return current path described by the signal trace 302 and the GND plane 332 or V_{CC} plane 334. The signal trace 302 on the bottom surface 306 is referenced to power plane V_{CC} 334 that is coupled to the GND plane 332 through decoupling capacitor 350. This coupling between the two planes will keep the high frequency impedance close to constant for the transition from one return plane to another plane of a different DC voltage.

[0079] Internally mounting Z-directed components in a PCB greatly facilitates the PCB technique of using outer PCB ground planes for EMI reduction. With this technique, signals are routed on the inner layers as much as possible. FIG. 11 illustrates one embodiment of this technique. PCB 400 is comprised of, from top to bottom, top ground layer 402, internal signal layer 404, internal signal layer 406 and bottom ground layer 408. Ground layers 402 and 408 are on the top and bottom surfaces 400t and 400b of PCB 400. A mounting hole 410, shown as a through-hole, extends between the top and bottom surfaces 400t and 400b. Z-directed component 420 is shown flush mounted in PCB 400. Z-directed component 420 comprises body 422 having a center region 424 intermediate the top 422t and bottom 422b of body 422 and two side channels 425 and 427 on side surface 422s.

[0080] Side channels 425 and 427 and wall 411 of hole 410 form plating wells 413 and 415 respectively. Center region 424 is positioned within body 422 and extends a distance approximately equal to the distance separating the two internal signal layers 404 and 406. Side channel 425 extends from the bottom surface 422b of body 422 to internal signal level 406 while side channel 427 extends from top surface 422t of body 422 to internal signal level 404. Here, side channels 425 and 427 extend only along a portion of side surface 422s of body 422. Conductive channel 426 extends through center region 424 but does not extend to the top and bottom surfaces 422t, 422b of body 422. FIG. 5H illustrates a partial channel similar to side channel 427. Conductive channel 426 has conductive traces 428t and 428b extending from the top 426t and bottom 426b of conductive channel 426 to side channels 427 and 425, respectively. While illustrated as separate elements, conductive channel 426 and traces 428t, 428b may be one integrated conductor electrically interconnecting side channels 425, 427. As shown, conductive trace 428b is connected to internal signal layer 406 via plated side channel 425 and well 413 while trace 428t connects to internal signal level 404 via side channel 427 and well 415. Ground layers 402 and 408 are not connected to Z-directed component 420 and are spaced away from mounting hole 410 as previously described for FIGS. 8 and 10. As shown by double headed dashed arrow 430, a signal on signal layer 406 can be via'd to signal layer 404 (or vice versa) via Z-directed component 420 through a path extending from well 413, side channel 425, trace 428b, conductive channel 426, trace 428t, side channel 427, and well 415 to allow the signal to remain on the inner layers of PCB 400 with ground layers 402 and 408 providing shielding.

[0081] Z-Directed Decoupling Capacitors

[0082] FIGS. 12 and 13 illustrate two additional example Z-directed components in the form of decoupling capacitors. In FIG. 12, a Z-directed capacitor 500 is shown with a body

502 having a conductive channel 504 and two side channels 506 and 508 extending along its length similar to those previously described. Conductive channel 504 is shown connected to a signal 526. Vertically oriented interleaved partial cylindrical sheets 510, 512 forming the plates of Z-directed capacitor 500 are connected to reference voltages such as voltage V_{CC} and ground (or any other signals requiring capacitance) and are used with intervening layers of dielectric material (not shown). Partial cylindrical sheet 510 is connected to plated channel 506 which is connected to ground 520. Partial cylindrical sheet 512 is connected to plated channel 508 which is connected to supply voltage V_{CC} 522. Sheets 510, 512 may be formed of copper, aluminum or other material with high conductivity. The material between the partial cylindrical sheets is a material with dielectric properties. Only one partial cylindrical sheet is shown connected to each of V_{CC} 522 and ground 520; however, additional partial cylindrical sheets may be provided to achieve the desired capacitance/voltage rating.

[0083] Another embodiment of a Z-directed capacitor is shown in FIG. 13 using stacked support members connected to voltage V_{CC} or ground. Z-directed capacitor 600 is comprised of center conductive channel 601 and a body 605 comprised of a top member 605t, a bottom member 605b, and a plurality of support members 610 (illustrated as disks) between the top and bottom members 605t, 605b.

[0084] Center conductive channel 601 extends through openings 615 in the assembled Z-directed capacitor 600 and openings 602t and 602b, all of which are sized to closely receive the center conductor. Center conductive channel 601 is electrically connectable to conductive traces 603t and 603b on the top and bottom portions 605t, 605b forming a signal path for signal 626. This connection is made by plating or soldering. Center conductive channel 601 is connected to signal 626 via conductive trace 603t. The bottom end of conductive channel 601 is connected in a similar fashion to a signal trace (not shown) via conductive trace 603b.

[0085] Opposed openings 607t and 608t are provided at the edge of top portion 605t. Bottom portion 605b is of similar construction as top portion 605t having opposed openings 607b and 608b provided at the edge. Between top and bottom portions 605t, 605b are a plurality of support members 610, which provide the capacitive feature. Support members 610 each have at least one opening 613 at their outer edge and an inner hole 615 allowing for passage of conductive channel 601 therethrough. As shown, two opposed openings 613 are provided in each support member 610. When assembled, the opposed openings 607t, 607b, 608t, 608b, and 613 align to form opposed side channels 604 and 608 extending along the side surface of Z-directed capacitor 600. Side channel 604 is shown connected to reference voltage such as ground 620 and side channel 606 to another reference voltage such as V_{CC} 622. Support members 610 may be fabricated from a dielectric material and may be all of the same or varying thickness allowing for choice in designing the desired properties for Z-directed capacitor 600.

[0086] Annular plating 617 is provided on one of top and bottom surfaces of support member 610 or, if desired, on both surfaces. Annular plating is shown on the top surface of each support member but location of the annular plating can vary from support member to support member. Annular plating 617 generally conforms to the shape of the support member and extends from one of the edge openings 613 toward the other if an additional opening is provided. The annular plate

617 is of a diameter or dimension or overall size that is less than the diameter, dimension or overall size of support member **610** on which it is affixed. While the plate **617** is described as annular, other shapes may also be used provided that the plating does not contact the center conductive channel or extend to the edge of the support member on which it is plated or otherwise affixed. The annular plate does contact one of the edge openings **613** but is spaced apart from the other openings if more than one channel is present in the side surface of the body of Z-directed capacitor **600**. Also, there is an opening **619** in annular plate **617** having a larger diameter than opening **615** in annular plate **617** through which conductive channel **601** passes. Opening **619** has a larger diameter than that of conductive channel **601** leaving annular plate **617** spaced apart from conductive channel **601**.

[0087] As illustrated, the support members **610** are substantially identical except that when stacked, alternate members are rotated 180 degrees with respect to the member above or below it. This may be referred to as a 1-1 configuration. In this way, alternate members will be connected to one or the other of the two side channels. As shown in FIG. 13, the annular plating on the upper one of the two support members **610** is connected to side channel **608** and voltage V_{CC} **622** while the annular plating on the lower one of the two support members **610** is connected to side channel **604** and ground **620**. Other support member arrangements may also be used such as having two adjacent members connected to the same channel with the next support member being connected to the opposite channel which may be referred to as a 2-1 configuration. Other configurations may include 2-2, 3-1 and are a matter of design choice. The desired capacitance or voltage rating determines the number of support members that are inserted between top and bottom portions **605a**, **605b**. Although not shown, dielectric members comprised of dielectric material and similarly shaped to support members **610** may be interleaved with support members **610**. Based on design choice, only a single channel may be used or more channels may be provided and/or the annular plating may be brought into contact with the center conductive channel and not in contact with the side channels. Again, the embodiments for Z-directed capacitors are for purposes of illustration and are not meant to be limiting.

[0088] With either design for a Z-directed capacitor, a second conductive channel may be provided in parallel with the first conductive channel that is disposed within the conductive plates to create a differential decoupling capacitor. Another embodiment of a Z-directed capacitor can be constructed from FIG. 12 or FIG. 13 by connecting the center conductive channel to one of the reference voltages at each support member that also has its annular plating connected to the same reference voltage. This may be accomplished simply by connecting the conductive channel to the annular plating as schematically illustrated by the jumper **621**. In practice, the annular opening **619** in the annular plate **617** would be sized so that the annular plate and conductive channel **601** would be electrically connected. This component may be placed directly below a power pin or ball of an integrated circuit or other surface mounted component for optimum decoupling placement.

[0089] Again, the Z-directed signal pass-through components illustrated in FIGS. 8-11 and the Z-directed decoupling capacitors illustrated in FIGS. 12 and 13 provide merely a few example applications of a Z-directed component. Those skilled in the art will appreciate that various other types of

Z-directed components may be utilized including, but not limited to, transmission lines, delay lines, T filters, decoupling capacitors, inductors, common mode chokes, resistors, differential pair pass throughs, differential ferrite beads, diodes, or ESD protection devices (varistors).

[0090] Extrusion Process for Manufacturing a Z-Directed Component

[0091] An extrusion process for manufacturing the Z-directed components on a commercial scale is provided. In the extrusion process, the bodies of the Z-directed components are formed from a material forming the component substrate. As needed, the substrate material may also be mixed with a binder material as is known in the art. As discussed above, a variety of different Z-directed components are contemplated herein including, but not limited to, transmission lines, delay lines, T filters, decoupling capacitors, inductors, common mode chokes, resistors, differential pair pass throughs, differential ferrite beads, diodes, and ESD protection devices (varistors). Accordingly, it will be appreciated that the substrate material used will depend on the Z-directed component desired. The substrate material may include a single dielectric material that has a relative permittivity from about 3, e.g., polymers, to over 10,000, e.g., barium titanate ($BaTiO_3$). For example, a material with a relatively high dielectric value may be used in a Z-directed decoupling capacitor and a material with a relatively low dielectric value may be used in a Z-directed signal pass-through component. If a Z-directed component is desired to have an inductive function or a delay line then a ferrite material may be selected that has a low or high relative permeability with a range of about 1 to about 50,000. If a Z-directed component is desired to have some degree of conductivity then a conductive material may be mixed with a dielectric material to create a desired resistance. Depending on the function of the Z-directed component desired, these or other compatible materials may be mixed together to form a component layer.

[0092] With reference to FIGS. 14A and 14B, an extrusion die **700** defining the shape of the Z-directed component layer (s) according to one embodiment is illustrated. Extrusion die **700** includes a chamber **703** having an inlet **701** and an outlet **702** for passing the component substrate material there-through. In the example embodiment illustrated, a generally cylindrical chamber **703** is used; however, as discussed above, many different shapes may be used. In this embodiment, an interior projection **704** is provided that forms a corresponding interior channel in the component layer(s). A pair of projections **705**, **706** along an edge **703e** of chamber **703** are also included that form a corresponding pair of side channels in the component layer(s). In the example embodiment illustrated, projection **704** is cylindrical and projections **705**, **706** are semi-cylindrical; however, any suitable shape may be used as desired depending on the desired shape of the channels in the component layer(s). Further, although one interior projection **704** and two side projections **705**, **706** are illustrated; any suitable number of side and/or interior projections may be used depending on the desired number of side and interior channels, respectively, through the component layer(s).

[0093] It will be appreciated that where extrusion die **700** includes one or more interior projections for forming an interior channel in the component layer(s), such as interior projection **704**, a support member **707** is needed to physically support the interior projection from one or more points along edge **703e** of chamber **703**. In the example embodiment illus-

trated, support member 707 connects interior projection 704 with both side projections 705, 706 to support interior projection 704.

[0094] One or more layers of the Z-directed component are formed by forcing a blank 708 containing the substrate material through extrusion die 700 using a ram (not shown). In one embodiment, blank 708 is composed of green (unfired) ceramic; however, various substrate materials may be used as discussed above. Specifically, blank 708 is pressed into inlet 701 through chamber 703 which causes the substrate material to take on the shape of chamber 703. As the substrate material is forced through chamber 703, projections 704, 705, 706 form the desired channels through the substrate material. A direct extrusion process may be used where extrusion die 700 is held stationary and the ram is moved towards it or an indirect extrusion process may be used where the ram is held stationary and extrusion die 700 is moved towards it. A combination of the two may be also used where the ram and die 700 are moved towards each other. Alternatively, a hydrostatic extrusion process may be used where fluid pressure is used to force blank 708 through die 700. Extrusion die 700 may be oriented horizontally, vertically or at any suitable angle thereto. Any conventional drive may be applied to provide the extruding force including a mechanical or hydraulic drive.

[0095] It will be appreciated that where one or more interior projections, such as projection 704, are included in extrusion die 700, the corresponding support member 707 will create an undesired gap in the extruded substrate material. Support member 707 is preferably thin in order to minimize the size of this gap. For example, when the extrusion die 700 illustrated in FIGS. 14A and 14B is used, the substrate material is divided in half by support member 707. With reference to FIG. 15A, which shows a cutaway view of chamber 703, one way to remove this gap, shown as gap 710, is to recombine the halves 708a, 708b of the substrate material in the output 702 of chamber 703 (or a separate chamber attached thereto). The diameter of chamber 703 (or width in the case of a chamber having a non-circular cross-section) may decrease slightly in the downstream direction D of extrusion past projections 704, 705, 706 in order to urge halves 708a, 708b toward each other. As shown in FIG. 15A, this causes gap 710 to reduce as the substrate material advances until halves 708a, 708b combine to eliminate gap 710. Further, the downstream edge of support member 707 may taper like a blade such that its thickness decreases in downstream direction D in order to promote recombination of halves 708a, 708b. The upstream edge of support member 707 may also taper to provide a cleaner cut into blank 708 in order to facilitate recombination.

[0096] It will be appreciated that care must be taken to prevent the channels formed by projections 704, 705, 706 from narrowing or losing their shapes as the substrate material advances. In the example embodiment shown in FIG. 15B, which shows a cutaway view of chamber 703, a movable element 712, such as a plug or rod, supports the downstream end of the substrate material as it advances to help prevent the channels from narrowing as gap 710 is eliminated. For instance, where the extrusion process is performed in a vertically downward direction, plug 712 supports the substrate material from below and lowers according to the speed of extrusion in order to maintain the shape of the substrate material. Projections 704, 705, 706 can also be extended in downstream direction D as desired to prevent the channels from losing their shape. Further, where some narrowing of the

channels in the substrate material is anticipated, it can be accounted for by initially making the channels slightly larger than desired and allowing them to narrow to their desired size and shape. In this manner, the substrate material exiting extrusion die 700 includes the desired channels therein but not the undesired gap 710 caused by support member 707.

[0097] With reference to FIG. 16, an alternative for forming interior channels in the component layer(s) without forming an undesired gap is to extrude the material in separate segments, such as halves, and then to combine the segments after extrusion. For example, where an extrusion die having an interior support member (such as support member 707 of extrusion die 700 shown in FIGS. 14A and 14B) is used, instead of recombining the segments in the output of the chamber as discussed above related to FIGS. 15A and 15B, the halves may be removed from the extrusion die and then combined. Further, where the segments of the extruded material to be combined are symmetrical, a common extrusion die may be used to extrude each segment separately. Conversely, where the segments are asymmetrical, multiple extrusion dies will be used. In the example embodiment illustrated, an extrusion die 720 having an inlet 721, and outlet 722 and a chamber 723 is used to form the component layer(s) in halves. Extrusion die 720 includes a projection 724 for forming an interior channel and a projection 726 for forming a side channel in the component layer(s). Projections 724, 726 are each positioned along an edge 723e of chamber 723 thereby eliminating the need for an interior support member, such as support member 707 shown in FIG. 14B. In the embodiment illustrated in FIG. 16, projection 726 is sized and shaped to form a complete side channel through each extruded segment. In contrast, projection 724 is sized and shaped to form only a partial interior channel through each extruded segment such that when the extruded segments are combined, the corresponding partial interior channels created by projection 724 are combined to form a complete interior channel through the component layer(s). Specifically, the void created by projection 724 in a first extruded segment is matched with a corresponding void created by projection 724 in a second extruded segment to create a complete interior channel in the component layer(s). The void created by projection 726 in the first extruded segment creates a first side channel in the component layer(s) and the void created by projection 726 in the second extruded segment creates a second side channel in the component layer(s).

[0098] The corresponding extruded segments can be combined by matably aligning the segments and then applying a substantially uniform radial pressure. In the unfired state, the extruded segments will tend to adhere to one another upon being pressed together by the applied radial pressure. An adhesive could also be used to join the segments to each other. The adhesive can be baked off when the substrate material is fired or it can be a high temperature adhesive that survives the firing process provided that the impurity in the substrate material caused by the adhesive will not inhibit performance of the Z-directed component.

[0099] Another alternative for forming interior channels in the component layer(s) without forming an undesired gap is to simply extrude the layer(s) using an extrusion die that does not include any interior projections that require support and then form the desired interior channel(s) after the extrusion process is completed. The desired interior channel(s) may be

formed by conventional methods known in the art such as drilling or laser cutting through the extruded substrate material.

[0100] After the substrate material has been extruded in the shape of the component layer(s), if desired, the substrate material can be partially fired in order to improve the strength of the material and to ensure that it will remain intact before proceeding with the remaining steps. After the substrate material is extruded, it may be cut into two or more individual component layers depending on the particular Z-directed component being made. For example, if the Z-directed component is intended to possess significant capacitance between any of the conductive paths the substrate material will be layered. Alternatively, if the Z-directed component only requires interior and/or side channels for signal and ground return paths, then the entire Z-directed component may be extruded at once. Conductive material can then be applied to the interior and/or side channels and across the top and/or bottom surface of the component to provide one or more traces for connection with the PCB as discussed below.

[0101] FIG. 17 shows a segment of extruded substrate material 730 ready to be cut. One option is to use a series of blades 732 spaced according to a predetermined distribution to create the component layers. In one embodiment, the component layers range in thickness from 0.5 mil to about 62 mil (about 0.0127 mm to about 1.57 mm), including all increments and values therebetween, depending on the application in which the Z-directed component will be used. Another option is to cut the extruded substrate material 730 using multiple passes of a single blade. In this embodiment, the thickness of each component layer is determined by controlling the timing of each pass of the blade. Each component layer may have substantially the same thickness or different thicknesses may be used. A feedback mechanism may be used to adjust the timing of the cuts in order to account for parameters that may change with blade usage, such as the kerf of the blade.

[0102] FIG. 18 shows a post-cut layer 740 of the Z-directed component formed by extrusion die 700. Layer 740 includes one center channel 742a and two side channels 742b, 742c that correspond with projections 704, 705 and 706, respectively. As discussed above, the shape of layer 740 and the number of channels 742 therein, as well as their placement and shape, can be altered by the changing the shape of the extrusion die chamber used including the number and placement of projections therein. At this point, layer 740 is ready to receive conductive material on at least one surface thereof. Conductive material may be applied to one or more of channels 742a, 742b, 742c, a top surface 740t and/or both top surface 740t and a bottom surface of layer 740. Layer 740 is transferred to a tool having restraining and locating ability, such as a conveyor belt, to receive conductive material. If it is desired to plate one or more side channels in the component layer 740, such as side channels 742b, 742c, layer 740 may be placed in a cavity 744 in a constraining plate 746 that has a side wall surface 748 that is spaced from the side channels 742b, 742c in the component layer 740 such that a gap 749 is formed therebetween (FIG. 19). This spacing allows conductive material to flow into gap 749 to plate the desired side channel(s) 742b, 742c. Another alternative to plate side channels 742b, 742c is to apply conductive material after the Z-directed component has been assembled by painting, jetting, sputter, or other known methods.

[0103] A number of different methods may be used to apply conductive material to layer 740. For example, in one embodiment, a mask is applied to top surface 740t that restricts the application of conductive material to selected portions of top surface 740t. Conductive material is then screened through the mask onto the component layer 740. FIG. 20 shows an example mask in the form of a physical mask 750 that is placed on top surface 740t of layer 740. The diagonal hatching included in FIG. 20 illustrates the openings in mask 750. Mask 750 includes a center opening 752 that permits conductive material to flow into and plate center conductive channel 742a. Mask 750 also includes a pair of peripheral openings 754a, 754b that permit conductive material to plate top surface 740t. Peripheral openings 754a, 754b are separated by a thin mask portion 756 that also separates center opening 752 from peripheral openings 754a, 754b. Portion 756 is required when one or more conductive channels through the interior of the layer 740 are desired in order to provide one or more interior openings in the mask such as center opening 752 in mask 750. Mask 750 includes a pair of scalloped portions 758a, 758b that are positioned above side channels 742b, 742c in the example embodiment illustrated. Scalloped portion 758b projects slightly further inward than scalloped portion 758a. As a result, in this example embodiment, conductive material is permitted to flow onto the portion of top surface 740t that connects with side channel 742b but conductive material is not permitted to connect with side channel 742c.

[0104] The resulting plated layer 740 utilizing example mask 750 is shown in FIG. 21 having conductive material 760 thereon. As shown, center channel 742a has been plated with conductive material 760. Top surface 740t of layer 740 has been plated to make a connection with side channel 742b but not side channel 742c. The mask 750 shown in FIG. 20 is intended to illustrate one example of a suitable mask. Alternative masks may be employed depending on such factors as the shape of the layer, the number of center channels and/or side channels that require plating, and the plating pattern desired for top surface 740t.

[0105] As an alternative to a physical mask, such as mask 750, a photoresist mask may be applied using photochemical methods known in the art. In this embodiment, a radiation-sensitive photoresist is applied to top surface 740t and then selectively exposed to a radiation source, such as X-ray or UV light. The photoresist is then developed to wash away the areas where the photoresist layer is not desired. It will be appreciated that positive or negative photoresists may be used as desired. Conductive material can then be screened through the photoresist mask onto top surface 740t of the component layer 740 such as by spin coating liquid conductive material on top of the photoresist mask. After the conductive material is applied, the remaining photoresist can then be removed.

[0106] In another embodiment, instead of using a mask, a selective jetting process is used to apply conductive material to top surface 740t and/or channel(s) 742. In this embodiment, liquid conductive material is applied to the component layer 740 using a fluid ejection mechanism as is known in the art. Where an etchable conductive material is used, another alternative is to spin coat or otherwise apply a layer of liquid conductive material across the entire top surface 740t and then selectively etch the conductive material from top surface 740t to form the desired conductive pattern thereon.

[0107] Another alternative is to first selectively apply a seed layer of conductive material to the component layer 740 and

then apply additional conductive material by electrolysis techniques. One suitable method for applying the seed layer includes the use of photochemical methods. A photoresist layer is applied across the entire top surface 740t of the Z-directed component layer 740 and then selectively exposed to a radiation source. The photoresist is then developed to wash away the areas where the photoresist layer is not desired. Again, positive or negative photoresists may be used as desired. Conductive material is then applied across the entire top surface 740t of the Z-directed component layer 740. The remainder of the photoresist is then etched away thereby also removing the conductive material from those areas where the seed layer is not desired. Electrolysis techniques are then applied to thicken the layer of conductive material on the component layer 740.

[0108] The various methods for applying conductive material to the Z-directed component layer described herein are equally applicable where it is desired to apply a material other than conductive material such as, for example resistive, magnetic, dielectric, or semi-conductive material to component layer 740. It will be appreciated that channel(s) 742 do not need to be plated after each layer is formed. Rather, channel(s) 742 may be filled with conductive material after the component layers are stacked together.

[0109] The Z-directed component is formed from a stack of component layers 740. Each layer may be formed from the same substrate material or some layers may be formed from different substrate materials. For example, a conveyor may be used to move all of the component layers 740 for stacking after they are formed. The outside features of the layers 740 may be used to align the layers 740 with each other. With reference to FIGS. 22A and 22B, for a Z-directed capacitor 762, each layer 740 is alternatively stacked by rotating it 180 degrees with respect to the layer 740 immediately below creating positive and negative terminals on two sides of the Z-directed component. The stacking is performed in a constraining plate that keeps the stack in position.

[0110] In some embodiments, a Z-directed component 764 may be desired that includes partial side channels 742 that are twisted or offset from each other between the top and bottom halves of the component 764 as shown in FIG. 23. This type of component may be desired in order to permit an interior signal to enter on one side of the Z-directed component 764 and exit at a 90 degree angle thereto without running into a side channel 742. This offset can be accomplished by rotating the layers 740 as they are stacked.

[0111] In one embodiment, once the component layers are stacked, they are compressed with moderate heat to create an aggregate that is solid enough to be removed from the constraining plate in which they are positioned to be fired later. For example, FIG. 24 shows a cutaway view of the stack of layers 740 positioned in a cavity 772 of a constraining plate 770. A movable component, e.g., a rod or a plug, applies a desired force to one end of the stacked layers to create the desired pressure profile for the materials chosen. In the example embodiment illustrated, opposing plugs 774, 776 apply pressure from opposite ends of the stacked layers 740. Heating elements can be embedded into the walls of cavity 772 in order to supply a desired temperature profile to the stacked layers 740. Alternatively, rather than applying moderate heat, a full firing process is performed in plate 770. However, this may be difficult due to the extreme temperatures that are subjected to the constraining elements.

[0112] In some embodiments, a chamfer, dome or other form of taper or lead-in of at least one of the top and bottom edge of the Z-directed component is desired in order to ease insertion of the Z-directed component into the mounting hole in the PCB. For example, FIG. 25A shows a Z-directed component 780 having a dome 782 formed on an end thereof. FIG. 25B shows a Z-directed component 784 having a chamfered end 786. The dome 782 or chamfer 786 may be part of the component or attached thereto. In one embodiment, the dome 782 or chamfer 786 is a separate part that is partially inserted into the mounting hole in the PCB. In this embodiment, the Z-directed component is then inserted behind the dome 782 or chamfer 786 to push it through the mounting hole causing the dome 782 or chamfer 786 to expand the mounting hole and prevent the component from cutting or tearing the PCB. Where the dome 782 or chamfer 786 is attached to the Z-directed component, it may be configured to remain attached to the Z-directed component following insertion into the mounting hole in the PCB or it may be used to facilitate insertion and then removed.

[0113] One method for forming the desired taper as part of the Z-directed component utilizes a plug 790 having a recess 792 formed in an end 794 thereof having a tapered rim 796 around a periphery of recess 792 as shown in FIG. 26. Tapered rim 796 is chamfered in the example embodiment illustrated; however, a domed, elliptical or rounded rim may also be used depending on the shape of the taper desired. Plug 790 is used to compress the stacked component layers as discussed above. When plug 790 applies a force to an end of the stacked layers, the end of the part is reflowed to have the desired geometry and the conductive path(s) on the end of the part are allowed to continue across or through the corresponding taper formed on the end of the part. As a result, the tapered end portion of the part can then be used to facilitate board to board electrical connections in multi-PCB applications. It will be appreciated that where the desired taper extends across multiple component layers, successive layers of the Z-directed component forming the taper will have decreasing diameters (or widths in the case of a component layer with a non-circular cross-section). Alternatively, the desired taper may be formed in a single component layer.

[0114] After the aggregate Z-directed component has been formed, a firing process is applied to solidify the part if it has not been done so already. The firing process also shrinks the part to its final dimensions. At this point, the Z-directed component can be tested for yield and performance and any additional processes may be performed as desired. For example, in some instances, the pressing and heating steps may cause burrs to form. Accordingly, in some embodiments, the Z-directed components are tumbled with various abrasive agents to smooth the corners and edges of the part. Further, resist areas may be added to the Z-directed component to keep the conductive materials from sticking to areas that are not intended to be conductive. Glue areas may be applied to the component to assist with retaining it in the PCB. Visible markings and/or locating features may be added to the Z-directed component to assist with assembly into the PCB.

[0115] Once production of the Z-directed component is complete, it is ready to be inserted into the mounting hole of the PCB. As discussed above, the component may be mounted normal to the plane of the PCB from the top or bottom surfaces or both surfaces, mounted at an angle thereto or inserted into the edge of the PCB between the top and bottom surfaces of the PCB. In some embodiments, the Z-di-

rected component is press fit into the mounting hole. This press fit may be in the form of an interference fit between the component and the mounting hole. After the Z-directed component is positioned in the mounting hole, a conductive plating bridge may be applied to connect one or more traces on the top and/or bottom surface of the component to a corresponding trace on the PCB. Further, where the Z-directed component includes side channels therein, such as side channels 742b, 742c, additional conductive plating may be applied to these side channels to form the desired signal connections between the Z-directed component and the PCB.

[0116] With reference to FIG. 27, in one embodiment, after a Z-directed component 800 is inserted into a mounting hole 802 in a PCB 804, an adhesive 806 is applied to a surface 808 of PCB 804 external to mounting hole 802. Adhesive 806 is positioned to contact a surface of Z-directed component 800 when it is inserted into mounting hole 802 in order to fix the location of Z-directed component 800 and prevent it from rotating or translating out of position.

[0117] With reference to FIGS. 28A and 28B, manufacturing variations in the thickness of the PCB and the length of the Z-directed component may prevent the Z-directed component from being perfectly flush with both the top and bottom surfaces of the PCB. As a result, in one embodiment, a conductive strip 812 is formed along a side surface 810s of a Z-directed component 810. Conductive strip 812 runs along side surface 810s to either the top or bottom surface of Z-directed component 810. It will be appreciated that conductive strip 812 may be applied after the Z-directed component 810 is formed. Alternatively, conductive strip 812 may be formed during fabrication of Z-directed component 810 such as by applying conductive material to a predetermined portion of the component layer(s) 740 as discussed above. In the example embodiment illustrated, conductive strip 812 runs along side surface 810s to a top surface 810t of Z-directed component 810. In this manner, conductive strip 812 forms a bridge between a trace 814 on the respective top or bottom surface of Z-directed component 810 and a trace 816 on a PCB 818 when the top or bottom surface of the Z-directed component extends past the corresponding top or bottom surface of the PCB. As a result, trace 814 on Z-directed component 810 is able to connect to trace 816 on PCB 818 even if the top or bottom surface of Z-directed component 810 is not flush with the corresponding top or bottom surface of PCB 818. In the example configuration illustrated in FIG. 28B, conductive strip 812 runs from top surface 810t of Z-directed component 810 to a point along side surface 810s that is below the top surface of the PCB 818. In one embodiment, conductive strip 812 extends into the side of Z-directed component 810 both to decrease its resistance and to ensure that it is not removed if another feature such as a taper is later applied to Z-directed component 810.

[0118] The foregoing description of several embodiments has been presented for purposes of illustration. It is not intended to be exhaustive or to limit the application to the precise forms disclosed, and obviously many modifications and variations are possible in light of the above teaching. It is understood that the invention may be practiced in ways other than as specifically set forth herein without departing from the scope of the invention. It is intended that the scope of the application be defined by the claims appended hereto.

1. A method for manufacturing a Z-directed component for insertion into a mounting hole in a printed circuit board, comprising:

extruding a substrate material according to the shape of the Z-directed component;
selectively applying a conductive material to the extruded substrate material; and
forming the Z-directed component from the extruded substrate material.

2. The method of claim 1, wherein extruding the substrate material according to the shape of the Z-directed component includes extruding a channel through the substrate material.

3. The method of claim 2, wherein the extruded channel is formed in an interior portion of the extruded substrate material.

4. The method of claim 2, wherein the extruded channel is formed along a longitudinal edge of the extruded substrate material.

5. The method of claim 1, further comprising extruding the substrate material in longitudinal segments and combining the longitudinal segments according to the shape of the Z-directed component.

6. The method of claim 5, wherein the longitudinal segments are combined after they are extruded.

7. The method of claim 5, wherein the longitudinal segments are combined in a continuous process downstream from their extrusion.

8. The method of claim 7, further comprising supporting the extruded longitudinal segments with a moving member from a downstream end of the substrate material as it advances.

9. The method of claim 1, further comprising:

dividing the extruded substrate material into a plurality of layers of the Z-directed component, wherein selectively applying the conductive material to the extruded substrate material includes applying the conductive material to a surface of at least one of the layers; and
combining a stack of the layers to form the Z-directed component.

10. The method of claim 9, wherein applying the conductive material to the surface of the at least one layer includes: applying a mask to a top surface of the at least one layer that restricts the application of conductive material to selected portions of the at least one layer; and
screening conductive material through the mask onto the at least one layer.

11. The method of claim 10, wherein the mask includes a physical mask placed on the top surface of the at least one layer.

12. The method of claim 10, wherein the mask includes a photoresist layer applied to and developed on the top surface of the at least one layer.

13. The method of claim 12, wherein screening conductive material through the mask onto the at least one layer includes spin coating liquid conductive material on top of the photoresist layer.

14. The method of claim 9, wherein applying the conductive material to the surface of the at least one layer includes spin coating a top surface of the at least one layer with liquid conductive material and then selectively etching conductive material from the top surface of the at least one layer.

15. The method of claim 9, wherein applying the conductive material to the surface of the at least one layer includes selectively jetting the conductive material onto the at least one layer.

16. The method of claim 9, wherein applying the conductive material to the surface of the at least one layer includes

applying a seed layer of conductive material onto a predetermined portion of the at least one layer and then applying additional conductive material by an electrolysis technique.

17. The method of claim **9**, wherein applying the conductive material to the surface of the at least one layer includes: positioning the at least one layer in a constraining plate having a side wall surface that is spaced from a side wall channel in the at least one layer forming a gap therebetween; and

applying conductive material in the gap formed between the side wall surface of the constraining plate and the side wall channel in the at least one layer to plate the side wall channel in the at least one layer with the conductive material.

18. The method of claim **9**, wherein combining the stack of the layers to form the Z-directed component includes heating and compressing the stacked layers to form an aggregate part.

19. The method of claim **18**, wherein the layers are compressed with a plug that includes a recess formed in an end thereof having a tapered rim around a periphery of the recess that forms a corresponding taper in at least one of a top surface

and a bottom surface of the Z-directed component when the stack of formed layers is combined.

20. The method of claim **1**, further comprising:

inserting the Z-directed component into the mounting hole in the printed circuit board; and

applying an adhesive to a surface of the printed circuit board external to the mounting hole, the adhesive contacting a surface of the Z-directed component when the Z-directed component is inserted into the mounting hole to prevent rotational and translational movement of the Z-directed component relative to the printed circuit board after insertion.

21. The method of claim **1**, further comprising forming a strip of conductive material along a side surface of the formed Z-directed component that connects to one of a top surface and a bottom surface of the Z-directed component to form a conductive bridge between the respective top or bottom surface of the Z-directed component and a trace on the printed circuit board.

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